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RDGD3162CSL3PEVM three-phase inverter reference design

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Document information

Information	Content
Keywords	GD3162, gate driver, power, inverter, automotive
Abstract	The RDGD3162CSL3PEVM three-phase inverter is a functional hardware power inverter reference design, which can be used as a foundation to develop a complete ASIL D compliant high voltage, high-power traction motor inverter for electric vehicles.

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| --- |
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2 RDGD3162CSL3PEVM
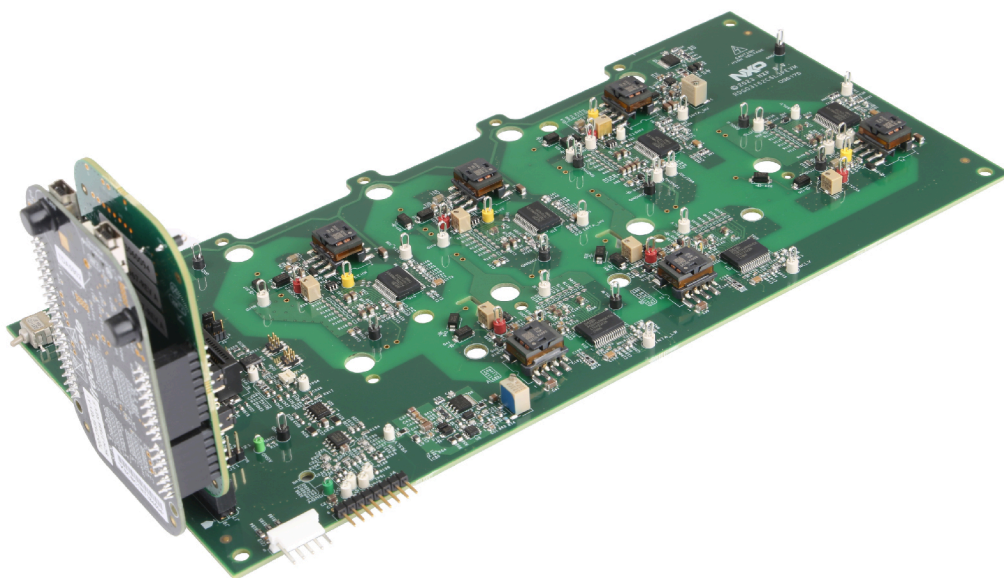
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Figure 1. RDGD3162CSL3PEVM

3   Introduction

This document is the user guide for the RDGD3162CSL3PEVM reference design. This document is intended for the engineers involved in the evaluation, design, implementation, and validation of the GD3162 single-channel gate driver for insulated-gate bipolar transistor (IGBT)/SiC metal-oxide-semiconductor field-effect transistor (MOSFET).

The scope of this document is to provide the user with information to evaluate the GD3162 single channel gate driver for IGBT/SiC. This document covers connecting the hardware, installing the software and tools, configuring the environment and using the kit.

The RDGD3162CSL3PEVM is a fully functional three-phase inverter evaluation board populated with six GD3162 gate drivers with fault management and supporting circuitry. This board supports serial peripheral interface (SPI) daisy chain communication for programming and communication with three high-side gate drivers and three low-side gate drivers independently, or all six gate drivers at the same time.

This board has low-voltage isolation and high-voltage isolation with gate drive integrated galvanic signal isolation. Other supporting features on the board include desaturation short-circuit detection, IGBT/SiC temperature sensing, onboard isolated flyback supplies, DC link bus voltage monitoring, phase current sensing, DC link bus current sense, and motor resolver excitation/processing. See GD3162 data sheet https://www.nxp.com/GD3162#documentation for more gate drive features. The data sheet requires a secure access rights request to download the document.

4   Finding kit resources and information on the NXP website

NXP Semiconductors provides online resources for this reference design and its supported devices on http://www.nxp.com.

The information page for the RDGD3162CSL3PEVM reference design is at http://www.nxp.com/RDGD3162CSL3PEVM. The information page provides overview information, documentation, software and tools, parametrics, ordering information and a **Getting Started** tab. The **Getting Started** tab provides quick reference information applicable to using the RDGD3162CSL3PEVM reference design, including the downloadable assets referenced in this document.

4.1   Collaborate in the NXP community

The NXP community is for sharing ideas and tips, ask and answer technical questions, and receive input on just about any embedded design topic.

The NXP community is at http://community.nxp.com.

5   Getting ready

Working with the RDGD3162CSL3PEVM requires kit contents and a Windows PC workstation with FlexGUI 2 software installed.

5.1   Kit contents

• Assembled and tested RDGD3162CSL3PEVM (three-phase inverter populated with 5.0 V compatible gate driver devices) board in an antistatic bag
• KITGD316xTREVB 3.3 V to 5.0 V translator with FRDM-KL25Z MCU board with micro-USB cable
• Quick start guide

5.2 Additional hardware

In addition to the kit contents, the following hardware is beneficial when working with this reference board.

- Microcontroller for SPI communication
- Compatible Bosch compact silicon carbide line (CSL) B-sample SiC MOSFET module
- DC link capacitor compatible with SiC MOSFET module
- HV power supply with protection shield and hearing protection
- Current sensors for monitoring each phase current
- 12 V, 1.0 A DC power supply
- 4-channel oscilloscope with appropriate isolated probes

5.3 Windows PC workstation

This reference design requires a Windows PC workstation. Meeting these minimum specifications produces great results when working with this evaluation board.

- USB-enabled computer with Windows 10 or higher operating system

5.4 Software

Installing software is necessary to work with this reference design. All listed software is available on the information page at http://www.nxp.com/RDGD3162CSL3PEVM.

- FlexGUI 2 software for using with KITGD316xTREVB MCU/translator board
- S32S Design Studio IDE for power architecture
- Automotive Math and Motor Control Library (AMMCLib)
- FreeMASTER 2.0 runtime debugging tool
- Motor control application tuning (MCAT)
- Example code, GD3162 device driver notes, and GD31xx driver example code

6 Getting to know the hardware

6.1 RDGD3162CSL3PEVM features

- Capability to perform double pulse and short-circuit tests on all phases (using J5 and J6) using KITGD316xTREVB and FlexGUI 2; see schematics and FlexGUI 2 pulse tab (Figure 29 and Figure 31)
- Evaluation board designed for and populated with GD3162 gate drivers and protection circuitry
- Capability to connect to Bosch CSL B-sample SiC specific modules for full three-phase evaluation and development (see Figure 9 for specific module pin placement)
- Daisy chain SPI communication × 3 - 2 channel (three high-side gate drivers and three low-side gate drivers) or × 6 - 1 channel (all six gate drivers)
- Variable flyback VCC power supply with GND reference and variable negative VEE supply
- Easy access to power, ground, and signal test points
- 2 × 32 peripheral component interconnect express (PCIe) socket for interfacing MCU control (MPC5775B/E-EVB, MPC5777C-DEVB, or MPC57744P); see Figure 32 and Figure 33
- Optional connection for DC bus voltage and current monitoring
- Phase current feedback connections
- Resolver signal connector

UM11996

User manual

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Rev. 2.0 — 16 October 2024

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Document feedback

4 / 41

6.2 Kit featured components

6.2.1 Voltage domains, GD3162 pinout, logic header, and SiC pinout

Low-voltage domain is an externally supplied 12 V DC (VPWR) primary supply for nonisolated circuits, typically supplied by a vehicle battery. A 5 V regulator supplies VDD to GD3162 gate drive devices. The low-voltage domain includes the interface between the MCU and GD3162 control registers and logic control.

Low-side driver and high-side driver domains are isolated high-voltage driver control domains for SiC MOSFET or IGBT single phase connections and control circuits. Pins on the bottom of the board are designed to connect easily to a compatible three-phase SiC MOSFET or IGBT module.
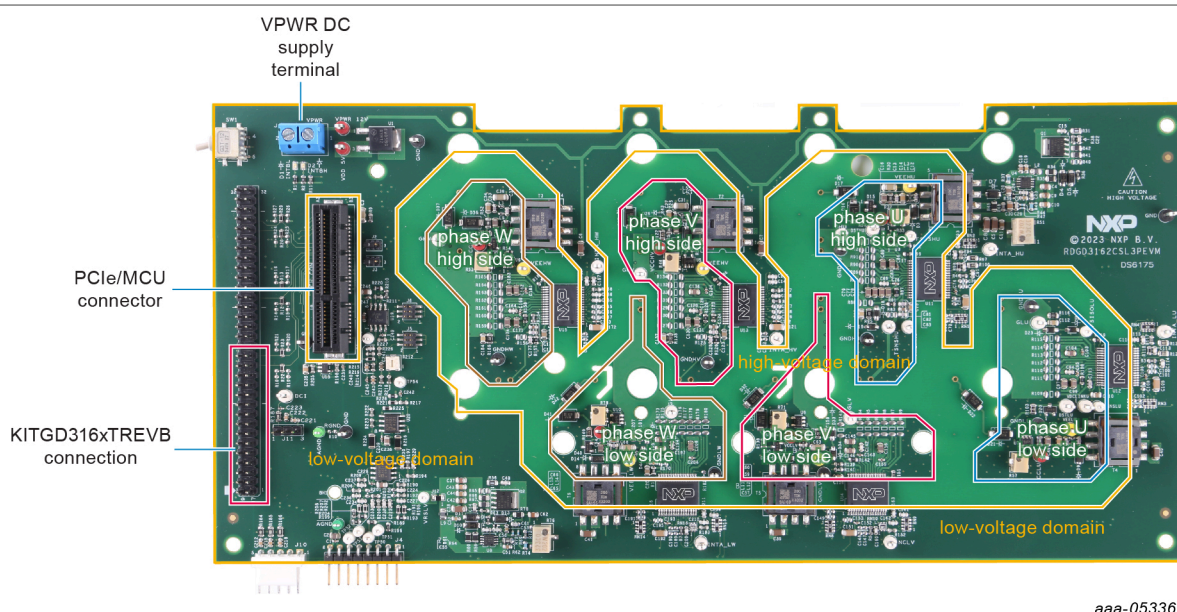
Figure 2. RDGD3162CSL3PEVM three-phase inverter board voltage domains and interfaces

6.2.2 GD3162 pinout and MCU interface pinout

See GD3162 advanced IGBT/SiC gate driver data sheet for specific information about pinout, pin descriptions, specifications, and operating modes. VPWR DC supply terminal is a low-voltage input connection for supplying power to the low-voltage nonisolated die and related circuitry. Typically supplied by vehicle battery +12 V DC.

MCU connector is a 2 × 32-pin PCIe interface connector for use with either MPC5775B/E-EVB or MPC5744P or MPC5777C 32-bit MCU board or any other MCU of preference. An MCU is needed for SPI communication and control of advanced IGBT/SiC gate drive devices (GD3162).

KITGD316xTREVB included with the kit (MCU and translator) can be attached to this board at the bottom of the dual row header pin interface. All gate drivers can be accessed via SPI control using FlexGUI 2 software.

Note: *Double pulse and short-circuit tests can be conducted on all phases thanks to onboard jumpers. See FlexGUI 2 pulse tab [Figure 29](#) and [Figure 31](#).*
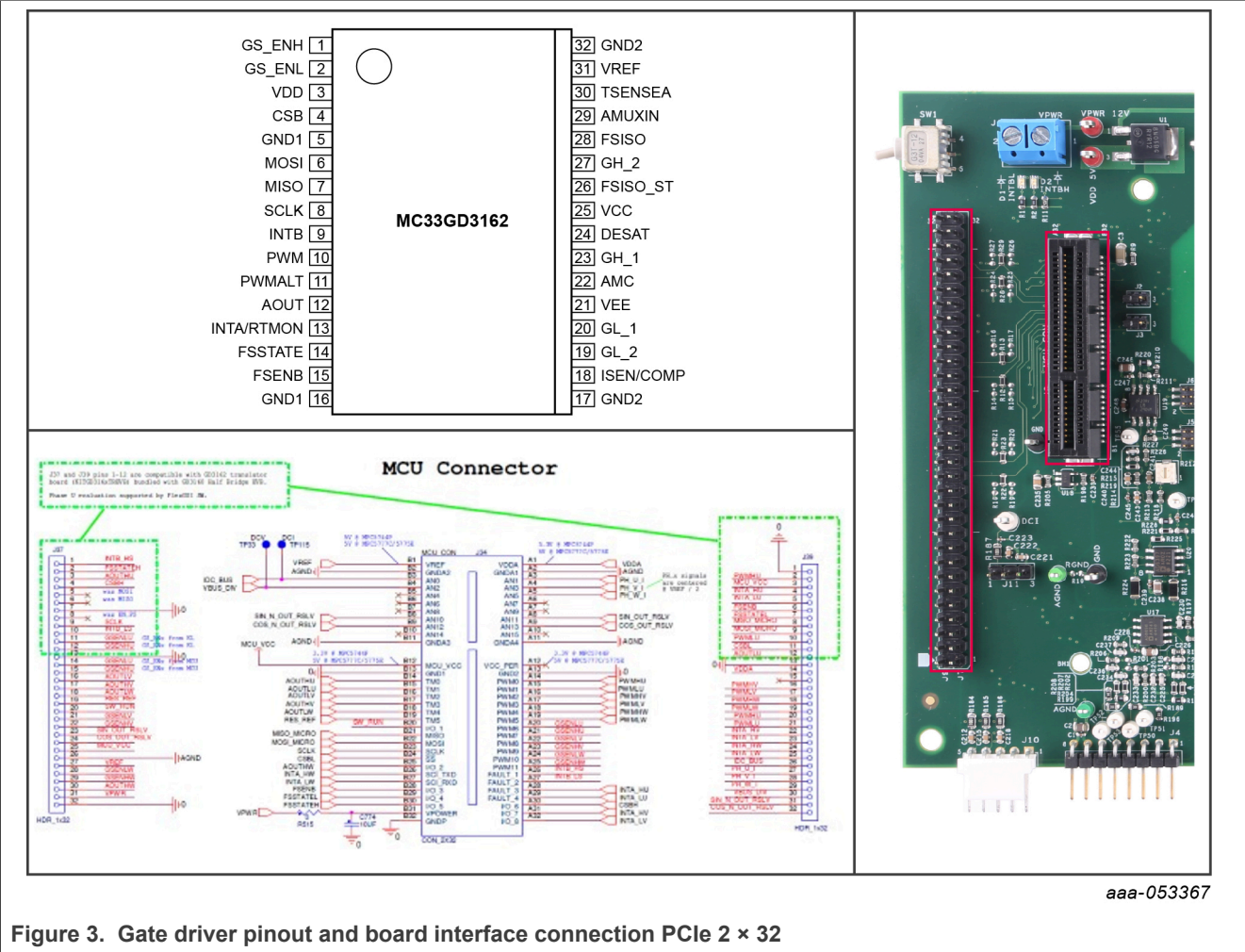
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Figure 3. Gate driver pinout and board interface connection PCIe 2 × 32

Table 1. PCIe MCU connector pin definitions

Pin	Name	Function
A1	VDDA	voltage reference resolver circuit
A2	GNDA1	analog ground
A3	PH_U_I	current feedback phase U
A4	PH_V_I	current feedback phase V
A5	PH_W_I	current feedback phase W
A6	n.c.	not connected
A7	n.c.	not connected
A8	SIN_OUT_RSLV	sine resolver signal
A9	COS_OUT_RSLV	cosine resolver signal
A10	n.c.	not connected
A11	GNDA4	analog ground
A12	VCC_PER	5.0 V MCU not connected

Table 1. PCIe MCU connector pin definitions...*continued*

Pin	Name	Function
A13	GND2	ground
A14	PWMHU	pulse width modulation (PWM) high-side phase U
A15	PWMLU	pulse width modulation low-side phase U
A16	PWMHV	pulse width modulation high-side phase V
A17	PWMLV	pulse width modulation low-side phase V
A18	PWMHW	pulse width modulation high-side phase W
A19	PWMLW	pulse width modulation low-side phase W
A20	GSENLU	GD3162 gate strength enable low-side phase U
A21	GSENHU	GD3162 gate strength enable high-side phase U
A22	GSENLV	GD3162 gate strength enable low-side phase V
A23	GSENHV	GD3162 gate strength enable high-side phase V
A24	GSENLW	GD3162 gate strength enable low-side phase W
A25	GSENHW	GD3162 gate strength enable high-side phase W
A26	INTB_HS	GD3162 fault reporting for high-side gate drive devices
A27	INTB_LS	GD3162 fault reporting for low-side gate drive devices
A28	INTA_HU	GD3162 fault reporting and real-time monitoring high-side phase U
A29	INTA_LU	GD3162 fault reporting and real-time monitoring low-side phase U
A30	CSBH	chip select bar to high gate drive devices
A31	INTA_HV	GD3162 fault reporting and real-time monitoring high-side phase V
A32	INTA_LV	GD3162 fault reporting and real-time monitoring low-side phase V
B1	VREF	voltage reference from MCU
B2	GNDA2	analog ground
B3	IDC_BUS	optional DC bus current measurement from DC bus current filter
B4	VBUS_DIV	optional DC bus voltage divider monitoring (not used by default)
B5	n.c.	not connected
B6	n.c.	not connected
B7	n.c.	not connected
B8	SIN_N_OUT_RSLV	sine resolver signal
B9	COS_N_OUT_RSLV	cosine resolver signal
B10	n.c.	not connected
B11	GNDA3	analog ground
B12	MCU_VCC	MCU VCC regulator voltage
B13	GND1	ground
B14	AOUTHU	GD3162 analog output signal high-side U phase
B15	AOUTLU	GD3162 analog output signal low-side U phase
B16	AOUTLV	GD3162 analog output signal low-side V phase

Table 1. PCIe MCU connector pin definitions...*continued*

Pin	Name	Function
B17	AOUTHV	GD3162 analog output signal high-side V phase
B18	AOUTLW	GD3162 analog output signal low-side W phase
B19	RES_REF	resolver reference voltage
B20	SW_RUN	signal from onboard switch demo mode
B21	MISO_MICRO	SPI slave out signal
B22	MOSI_MICRO	SPI slave in signal
B23	SCLK	SPI clock
B24	CSBL	chip select bar to low-side gate drivers
B25	AOUTHW	GD3162 analog output signal high-side W phase
B26	INTA_HW	GD3162 fault reporting and real-time monitoring high-side phase W
B27	INTA_LW	GD3162 fault reporting and real-time monitoring low-side phase W
B28	FSENB	fail-safe state enable bar
B29	FSSTATEL	fail-safe state low-side
B30	FSSTATEH	fail-safe state high-side
B31	VPWR	VPWR/VSUP 12 V voltage supply (low-voltage domain)
B32	GNDP	ground connection (low-voltage domain)

6.2.3 Test points

All test points are clearly marked on the board. Figure 4 shows the location of various test points.

Figure 4. RDGD3162CSL3PEVM test points
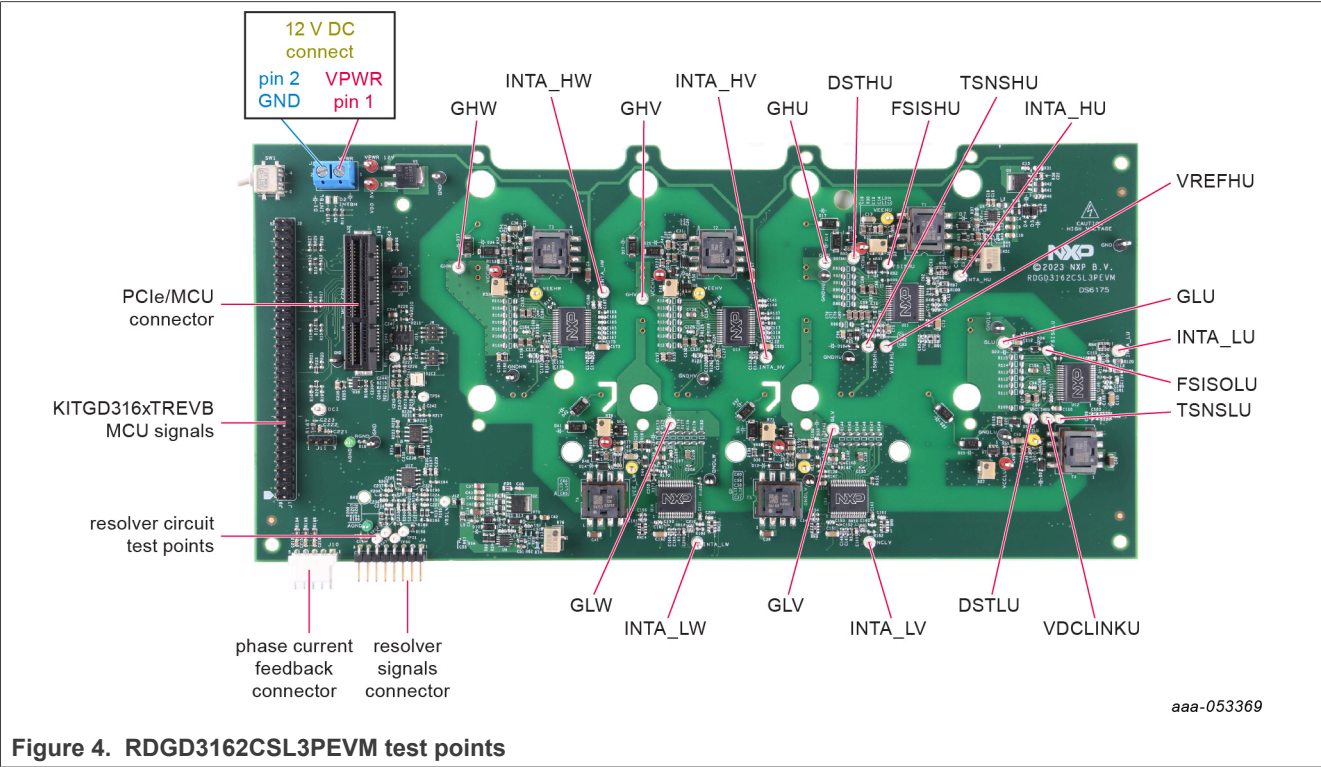
Table 2. Test points

Test point name	Function
DSTHU	DESAT high-side U phase V_{CE} desaturation connected to DESAT pin circuitry
DSTLU	DESAT low-side U phase V_{CE} desaturation connected to DESAT pin circuitry
FSISHU	FSISO connection high-side U phase
FSISLU	FSISO connection low-side U phase
GHU	gate high-side U phase, which is the charging pin of the IGBT gate
GHV	gate high-side V phase, which is the charging pin of the IGBT gate
GHW	gate high-side W phase, which is the charging pin of the IGBT gate
GLU	gate low-side U phase, which is the charging pin of the IGBT gate
GLV	gate low-side V phase, which is the charging pin of the IGBT gate
GLW	gate low-side W phase, which is the charging pin of the IGBT gate
INTA – UVW HS and LS	INTA interrupt/real-time reporting output signal test points from each gate driver
Resolver circuit	test points for internal signals of the resolver circuit (see schematic for more information)
MCU signals	signal headers for analyzing all MCU signals (see schematic for signals)
TSNSHU	TSENSE high-side U phase connected to negative temperature coefficient (NTC) temperature sense

Table 2. Test points...*continued*

Test point name	Function
TSNSLU	TSENSE low-side U phase
VREFLU	5.0 V reference voltage test point low-side U phase
VREFHU	5.0 V reference voltage test point high-side U phase
VPWR	VSUP/VPWR test point low-voltage domain

6.2.4 Indicators

The RDGD3162CSL3PEVM contains LEDs as visual indicators on the board.

Figure 5. RDGD3162CSL3PEVM indicator locations
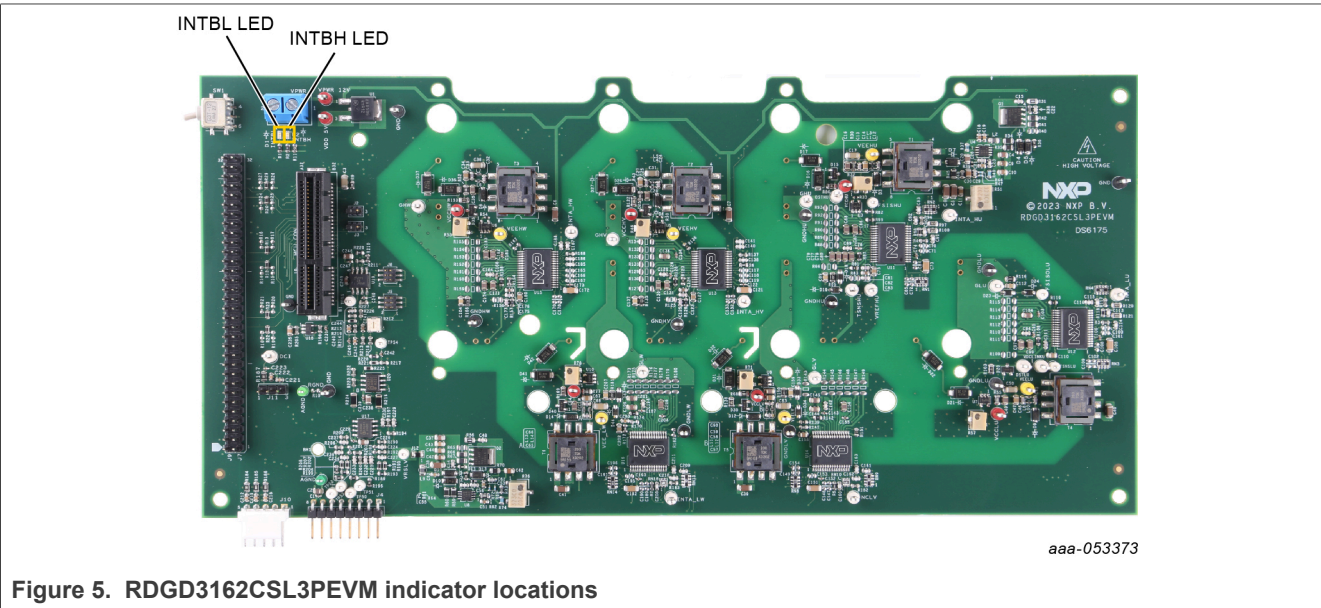
Table 3. RDGD3162CSL3PEVM indicator descriptions

Name	Description
INTBL LED	indicates that a GD3162 INTB fault interrupt has occurred on the low side
INTBH LED	indicates that a GD3162 INTB fault interrupt has occurred on the high side

UM11996

User manual **Rev. 2.0 — 16 October 2024** Document feedback

10 / 41

6.2.5 Connectors and jumpers

Figure 6. RDGD3162CSL3PEVM connector and jumper locations

Table 4. RDGD3162CSL3PEVM connector and jumper descriptions

Name	Description
J12	VPWR to VRSLV (12 V resolver excitation circuit) jumper closed to VPWR supply to power resolver logic
J2	jumper 1-2 default master output slave input (MOSI) - normal mode three device daisy chain three device high side, three device low side (× 3 - 2 channel) jumper 2-3 MOSI - six device daisy chain all six gate drivers daisy chained together (× 6 - 1 channel)
J3	jumper 1-2 default master input slave output (MISO) - normal mode three device daisy chain three device high side, three device low side (× 3 - 2 channel) jumper 2-3 MISO - six device daisy chain all six gate drivers daisy chained together (× 6 - 1 channel)
J5	KITGD316xTREVB PWMH connection selection to high-side gate drive PWM inputs; phase U, V, W; refer to schematic for details
J6	KITGD316xTREVB PWML connection selection to low-side gate drive PWM inputs; phase U, V, W; refer to schematic for details
J11	DC bus current measurement connection header; refer to schematic for details
J10 phase current feedback connector	current feedback connections from U, V, and W phases
J4 resolver signals connector	resolver excitation signals; refer to schematic for details
J9 and J8 MCU signals	two-row header of all MCU signals for debug and development; refer to schematic for details

UM11996

User manual **Rev. 2.0 — 16 October 2024** Document feedback

11 / 41

Table 4. RDGD3162CSL3PEVM connector and jumper descriptions...*continued*

Name	Description
J8 PCIe/MCU connector	2 × 32 PCIe connector for easy connection to MPC5777CDEVB or MPC5744P via PCIe cable (S32SDEV-CON18)
J1 VPWR terminal connector	used for external low-voltage power supply connection, typically 12 V V$_{BAT}$

6.2.6 Power supply test points

Figure 7. Power supply test point locations
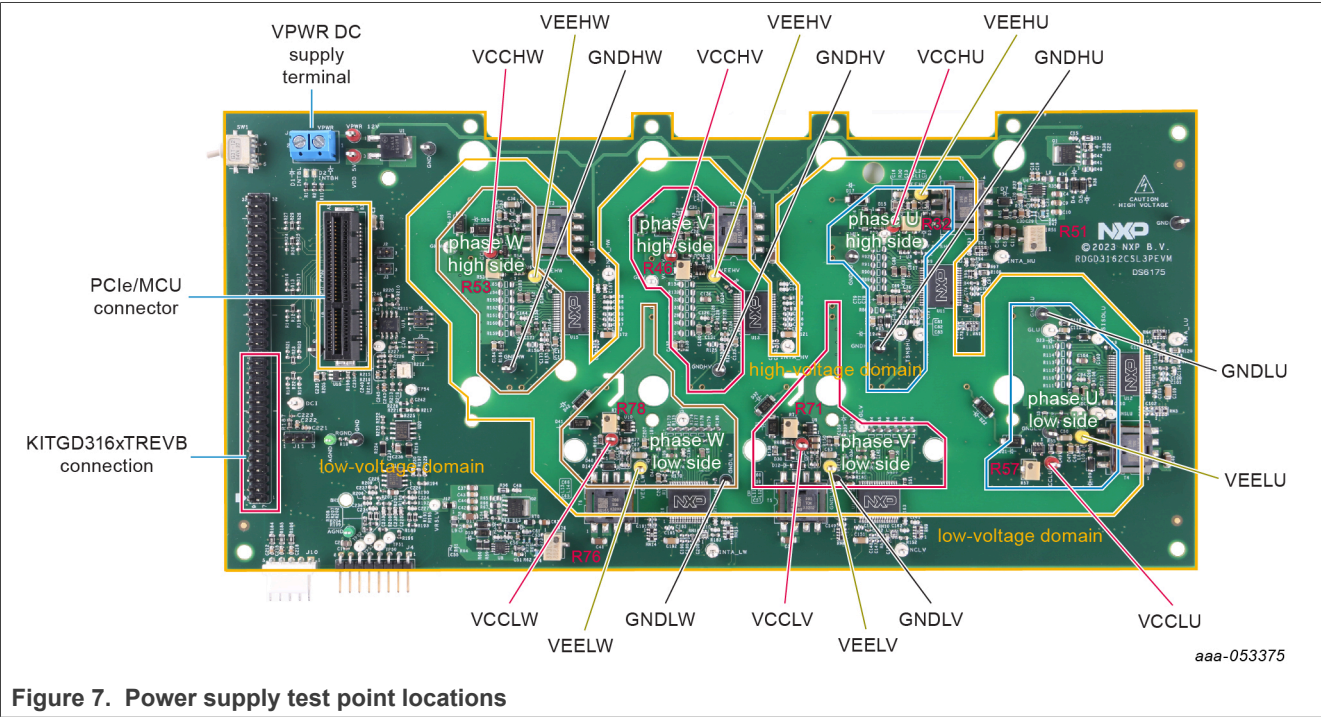
Table 5. Power supply test point descriptions

Name	Function
VCCHU	high-side phase U VCC voltage test point isolated positive voltage supply (9.3 V to 25 V) adjust with R51 potentiometer
GNDHU	isolated ground high-side phase U
VEEHU	negative gate supply voltage high-side phase U adjust with R32 potentiometer
VCCHV	high-side phase V VCC voltage test point isolated positive voltage supply (9.3 V to 25 V) adjust with R51 potentiometer
GNDHV	isolated ground high-side phase V
VEEHV	negative gate supply voltage high-side phase V adjust with R46 potentiometer

UM11996
User manual

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Document feedback

12 / 41

Table 5. Power supply test point descriptions...*continued*

Name	Function
VCCHW	high-side phase W VCC voltage test point isolated positive voltage supply (9.3 V to 25 V) adjust with R51 potentiometer
GNDHW	isolated ground high-side phase W
VEEHW	negative gate supply voltage high-side phase W adjust with R53 potentiometer
VCCLU	low-side phase U VCC voltage test point isolated positive voltage supply (9.3 V to 25 V) adjust with R76 potentiometer
GNDLU	isolated ground low-side phase U
VEELU	negative gate supply voltage low-side phase U adjust with R57 potentiometer
VCCLV	low-side phase V VCC voltage test point isolated positive voltage supply (9.3 V to 25 V) adjust with R76 potentiometer
GNDLV	isolated ground low-side phase V
VEELV	negative gate supply voltage low-side phase V adjust with R71 potentiometer
VCCLW	low-side phase W VCC voltage test point isolated positive voltage supply (9.3 V to 25 V) adjust with R76 potentiometer
GNDLW	isolated ground low-side phase W
VEELW	negative gate supply voltage low-side phase W adjust with R78 potentiometer
VPWR	+12 V DC VPWR low voltage positive supply connection
VPWR GND	VPWR low voltage supply ground connection (GND)

6.2.7 Gate drive resistors (not populated)

- RGH_1 - gate high resistor in series with the GH_1 pin at the output of the GD3162 high-side driver and IGBT/SiC gate that controls the strong turn-on current for IGBT/SiC gate.
- RGH_2 - gate high resistor in series with the GH_2 pin at the output of the GD3162 high-side driver and IGBT/SiC gate that controls the weak turn-on current for IGBT/SiC gate.
- RGL_1 - gate low resistor in series with the GL_1 pin at the output of the GD3162 low-side driver and IGBT/SiC gate that controls the strong turn-off current for IGBT/SiC gate.
- RGL_2 - gate low resistor in series with the GL_2 pin at the output of the GD3162 low-side driver and IGBT/SiC gate that controls the weak turn-off current for IGBT/SiC gate.
- RAMC - series resistor between IGBT/SiC gate and active Miller clamp (AMC) input pin of the GD3162 high-side/low-side driver for gate sensing and active Miller clamping.

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User manual Rev. 2.0 — 16 October 2024 Document feedback

13 / 41
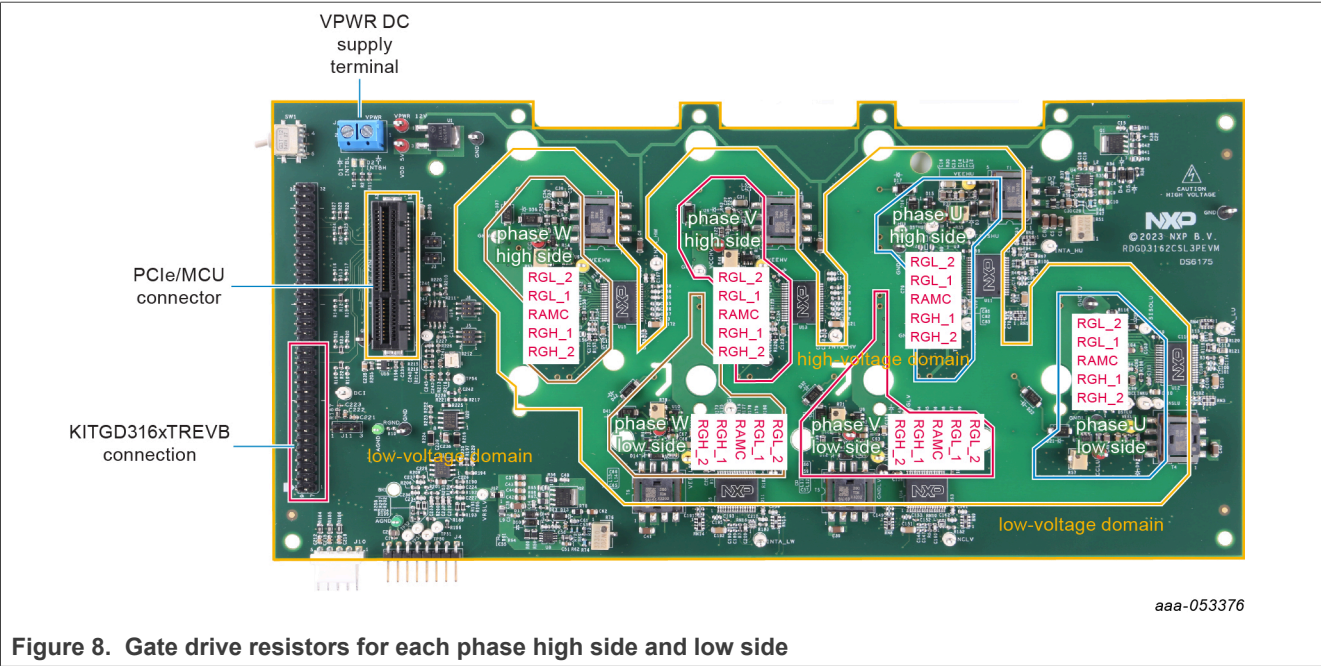
Figure 8. Gate drive resistors for each phase high side and low side

6.2.8 Bosch CSL B-sample SiC module pin connections
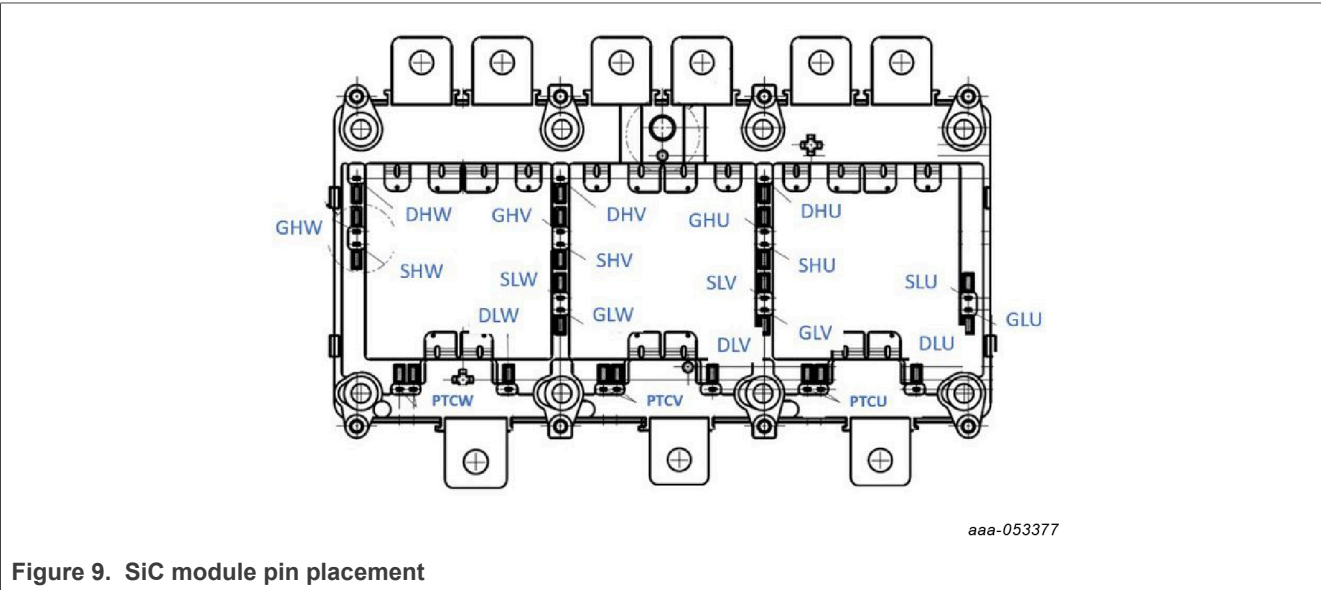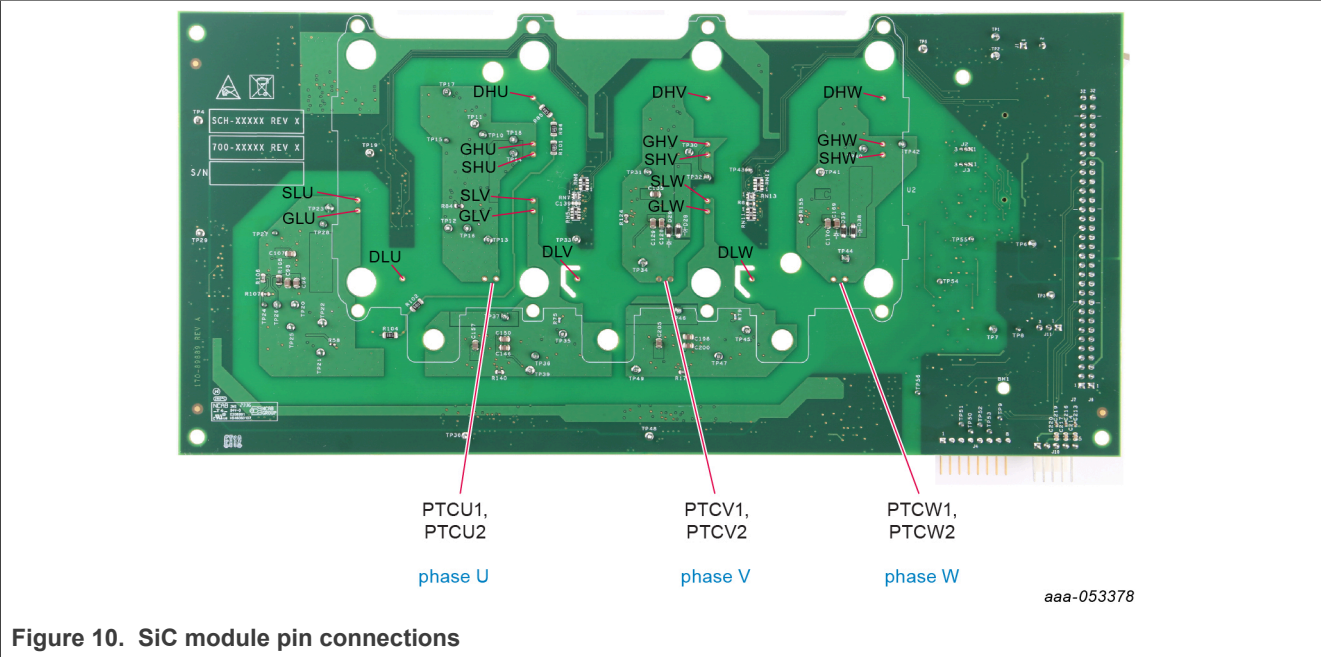

Figure 9. SiC module pin placement

**Figure 10. SiC module pin connections**

Table 6. SiC module pin connections

Connection name	Pin description
GHU	gate high-side U phase
DHU	drain connection high-side U phase
SHU	source connection high-side U phase
PTCU1	positive temperature coefficient (PTC) temperature sensor connection U phase (high-side TSENSEA)
PTCU2	PTC temperature sensor connection U phase (high-side isolated ground)
GLU	gate low-side U phase
SLU	source connection low-side U phase
DLU	drain connection low-side U phase
PTCV1	PTC temperature sensor connection V phase (high-side TSENSEA)
PTCV2	PTC temperature sensor connection V phase (high-side isolated ground)
GHV	gate high-side V phase
SHV	source connection high-side V phase
DHV	drain connection high-side V phase
GLV	gate low-side V phase
DLV	drain connection low-side V phase
SLV	source connection low-side V phase
PTCW1	PTC temperature sensor connection W phase (high-side TSENSEA)
PTCW2	PTC temperature sensor connection W phase (high-side isolated ground)
GHW	gate high-side W phase

Table 6. SiC module pin connections...*continued*

Connection name	Pin description
DHW	drain connection high-side W phase
SHW	source connection high-side W phase
GLW	gate low-side W phase
DLW	drain connection low-side W phase
SLW	source connection low-side W phase

6.3 Kinetis KL25Z Freedom board

The Freedom KL25Z is an ultra low-cost development platform for Kinetis L series MCU built on Arm Cortex-M0+ processor.

Figure 11. Freedom development platform
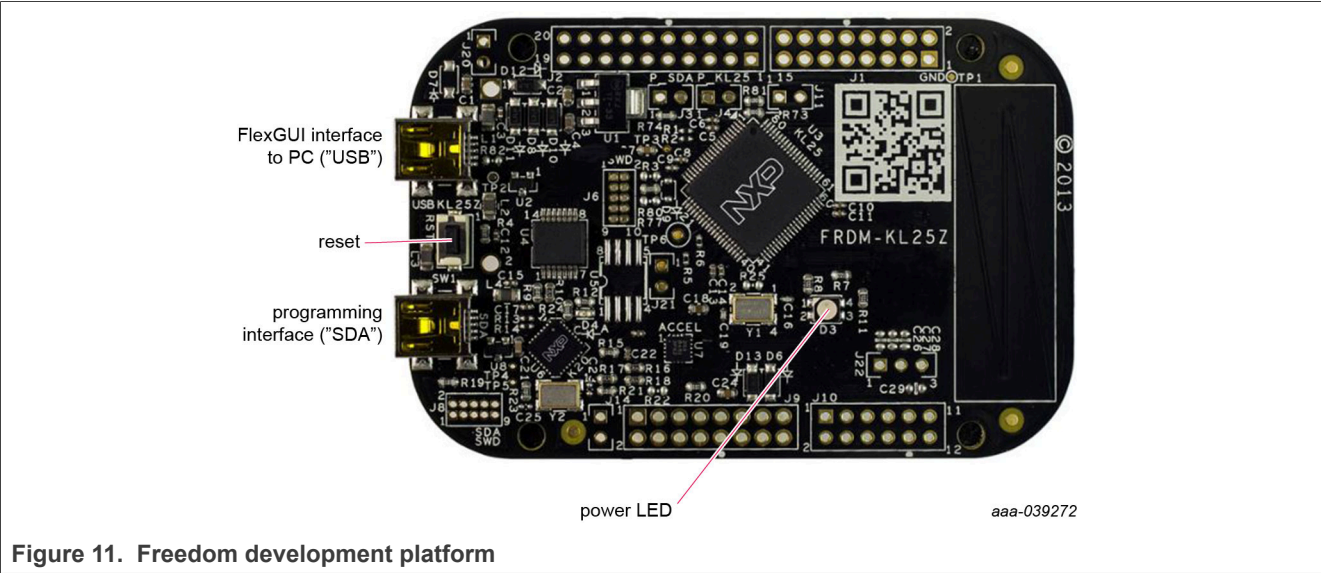
6.4 3.3 V to 5.0 V translator board

KITGD316xTREVB translator enables level shifting of signals from MCU 3.3 V to 5.0 V SPI communication.
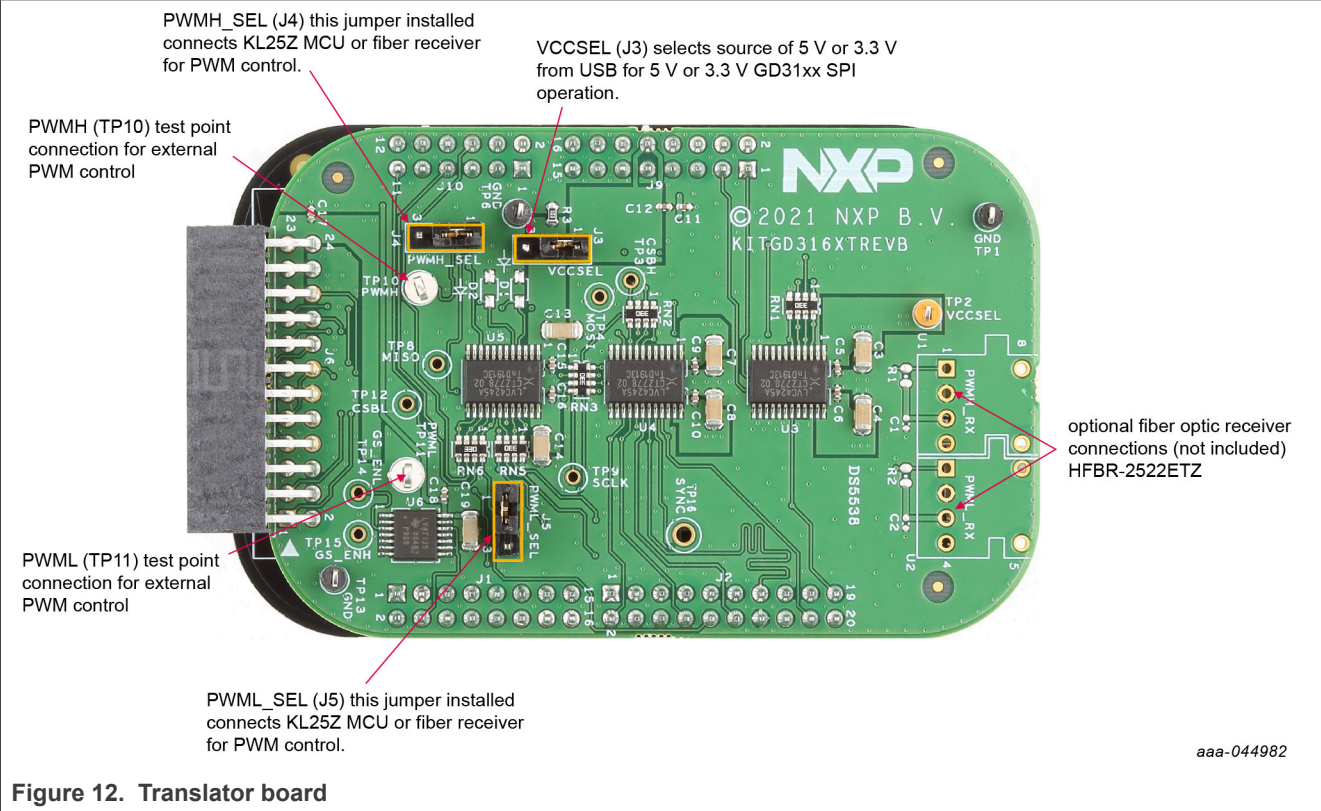
Figure 12. Translator board

Table 7. Translator board jumper definitions

Jumper	Position	Function
VCCSEL (J3)	1-2	selects 5.0 V for 5.0 V compatible gate drive
	2-3	selects 3.3 V for 3.3 V compatible gate drive
PWMH_SEL (J4)	1-2	selects PWM high-side control from KL25Z MCU
	2-3	selects PWM high-side control from fiber optic receiver inputs
PWML_SEL (J5)	1-2	selects PWM low-side control from KL25Z MCU
	2-3	selects PWM low-side control from fiber optic receiver inputs

7   Installing and configuring software and tools

Software for RDGD3162CSL3PEVM is distributed with the FlexGUI 2 tool (available on NXP.com). Necessary firmware comes preinstalled on the FRDM-KL25Z with the kit.

Even if you intend to test with other software or PWM, it is recommended to install this software as a backup or to help debugging.

7.1 Installing FlexGUI 2 for GD3162 on your computer

The latest version of FlexGUI 2 supports the GD3162 gate drivers. It is designed to run on any Windows 10 or higher based operating system. To install the software, do the following:

1. Go to www.nxp.com/FlexGUI and click **Download**.
2. When the FlexGUI 2 software page appears, click **Download** and select the version associated with your PC operating system.
3. The FlexGUI 2 wizard creates a shortcut. An NXP FlexGUI 2 icon appears on the desktop. Installing the device drivers overwrites any previous FlexGUI 2 installation and replaces it with a current version containing the GD3162 drivers. However, configuration files (.spi) from the previous version remain intact.

7.2 Configuring the FRDM-KL25Z microcode
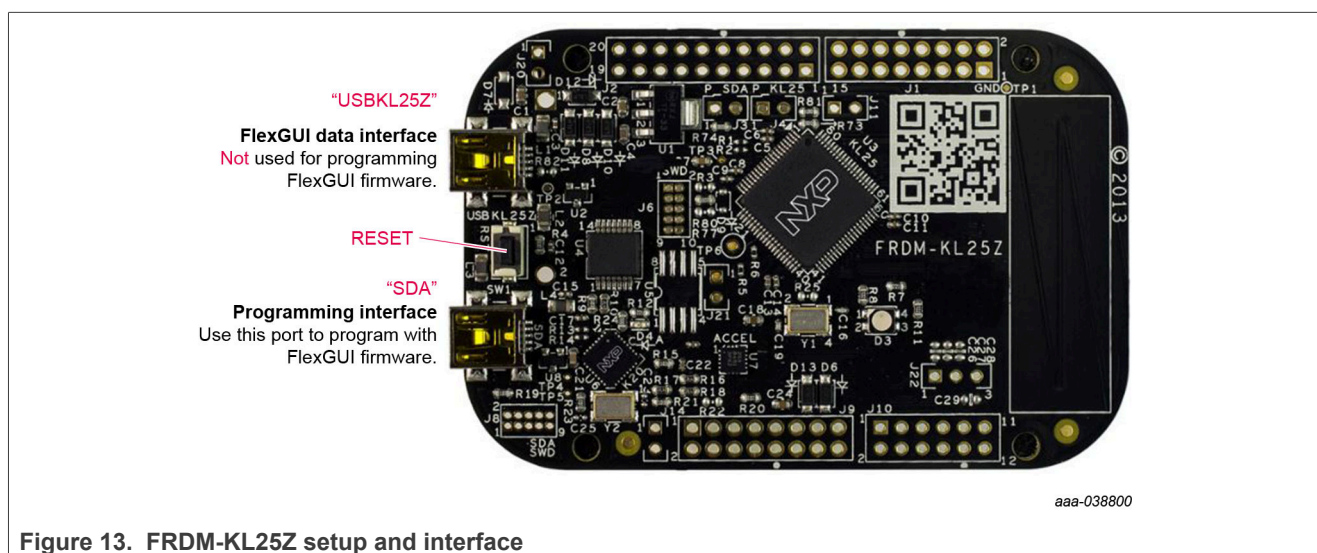
Figure 13. FRDM-KL25Z setup and interface

By default, the FRDM-KL25Z delivered with this kit is preprogrammed with the current and most up-to-date firmware available for the kit.

A way to check quickly that the microcode is programmed and the board is functioning properly, is to plug the KL25Z into the computer using a USB cable to the USBKL25Z port, open FlexGUI 2, and verify that the software version at the bottom is 1.4.3 or later (see Figure 13).

If a loss of functionality following a board reset, reprogramming, or a corrupted data issue, the microcode is rewritten per the following steps:

1. To clear the memory and place the board in bootloader mode, hold down the reset button while plugging a USB cable into the **OpenSDA** USB port.
2. Verify that the board appears as a BOOTLOADER device and continue with step 3. If the board appears as KL25Z, go to step 6.
3. Download the **Firmware Apps**.zip archive from the PEmicro OpenSDA webpage (http://www.pemicro.com/opensda/). Validate your email address to access the files.
4. Find the most recent MDS-DEBUG-FRDM-KL25Z_Pemicro_v118.SDA and copy/drag-and-drop into the **BOOTLOADER** device.
5. Reboot the board by unplugging and replugging the connection to the **OpenSDA** port. Verify now that the device appears as a KL25Z device to continue.
6. Locate the most recent KL25Z firmware, which is distributed as part of the FlexGUI 2 for GD3162 package.
   a. FlexGUI 2 for GD3162 download file is named in the form "flexgui2_fw_kl25z_gd3162_public_vx.x.x.bin".
   b. This .bin file is a product/family-specific configuration file for FRDM-KL25Z containing the pin definitions, SPI/PWM generation code, and pin-mapping assignments necessary to interface with the translator board as part of RDGD3162CSL3PEVM.
7. With the KL25Z still plugged through the **OpenSDA** port, copy/drag-and-drop the .bin file into the KL25Z device memory at PC drive FRDM-KL25Z (D:). Once done, disconnect the USB and plug into the other USB port, labeled **KL25Z**.
   a. The device does not appear as a distinct device to the computer while connected through the KL25Z USB port, which is normal.
8. The FRDM-KL25Z board is now fully set up to work with RDGD3162CSL3PEVM and the FlexGUI 2.
   a. There is no software stored or present on either the driver or translator boards, only on the FRDM-KL25Z MCU board.

All uploaded firmware is stored in nonvolatile memory until the reset button is hit on the FRDM-KL25Z. There is no need to repeat this process upon every power up, and there is no loss of data associated with a single unplug event.

7.3 Using FlexGUI 2 for GD3162

The FlexGUI 2 for GD3162 is available from http://www.nxp.com/FlexGUI as an evaluation tool demonstrating GD3162-specific functionality, configuration, and fault reporting. FlexGUI 2 also includes basic capacity for the RDGD3162I3PH5EVB to control an IGBT or SiC module, enabling double pulse or short-circuit testing.

SPI messages can be realized graphically or in hexadecimal format. CSB is selectable to daisy chain address. 3 low-side gate drivers and 3 high-side gate drivers simultaneously with (× 3 - 2 channel) selection or all 6 gate drivers with (× 6 - 1 channel). See Figure 14 for FlexGUI 2 for GD3162 internal register read and write access.

Starting FlexGUI 2 for GD3162

- FlexGUI 2 for GD3162 install program (NXP_GD316x_GUI_public-x.x.x.msi)
- Download FlexGUI 2 and run the install program on your PC.
- When you start the application, Figure 14 allows you to select the target application board, feature set (standard or daisy chain), target MCU, and USB interface. Leave all settings as shown.

Once the kit is selected, press Ok and select CONNECT FlexGUI 2 on following GUI page. Micro-USB cable must be attached from PC and KL25Z port on KL25Z MCU board.

See Table 4 for required jumper configuration to enable (× 3 - 2 channel) or (× 6 - 1 channel) SPI daisy chain operation.

Figure 14. Kit selection
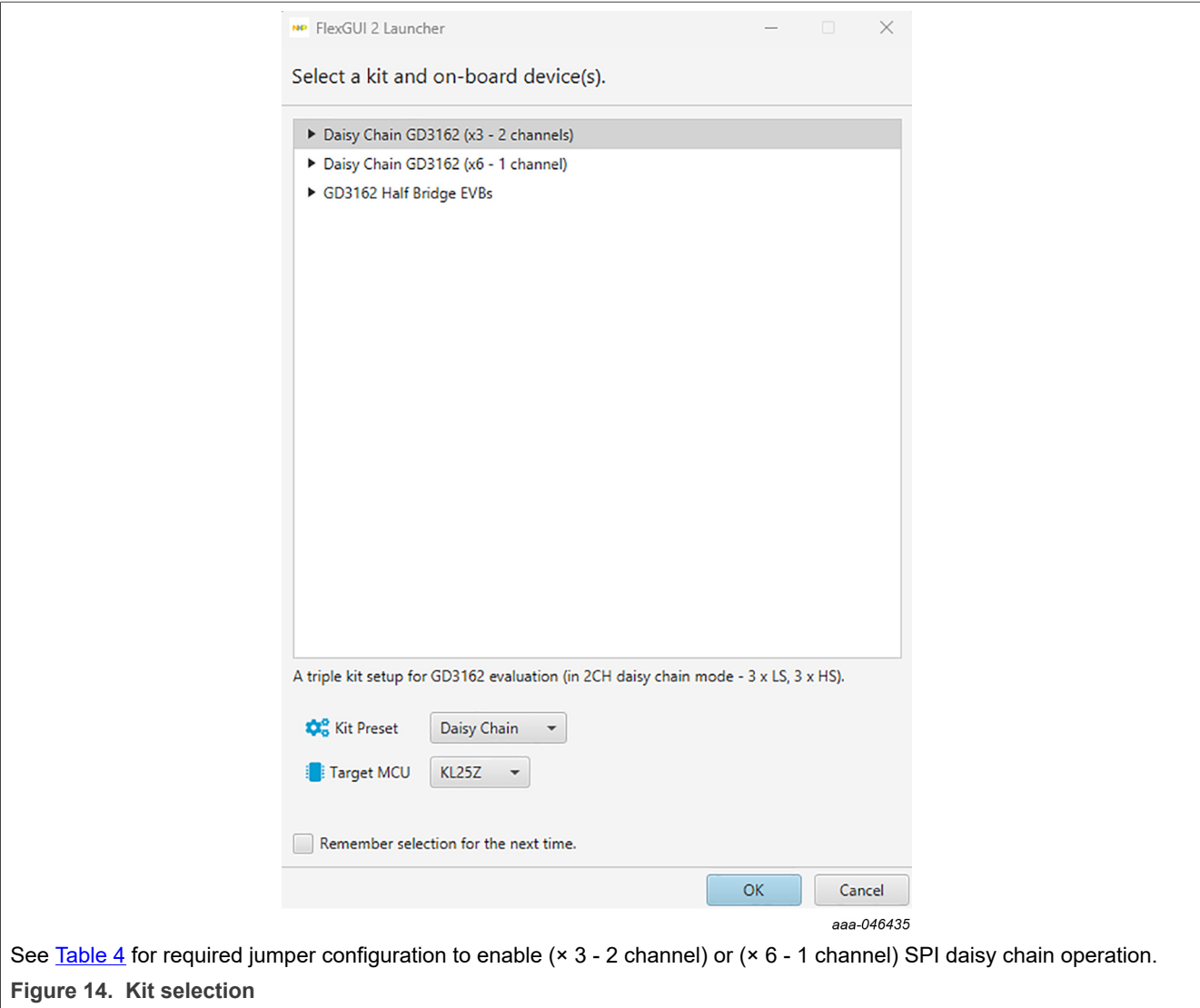
FlexGUI_2 connection

- Select FRDM-KL25Z COM port from the drop-down menu and select Connect to establish USB connection
  - If connection is not established, check USB cable connection between PC and KL25Z port and or scan again and select an alternate COM port for FRDM-KL25Z
  - If connection is not established, ensure that proper firmware is installed on FRDM-KL25Z MCU for FlexGUI 2 (refer to step 6 in Section 7.2)

Figure 15. FlexGUI 2 connection
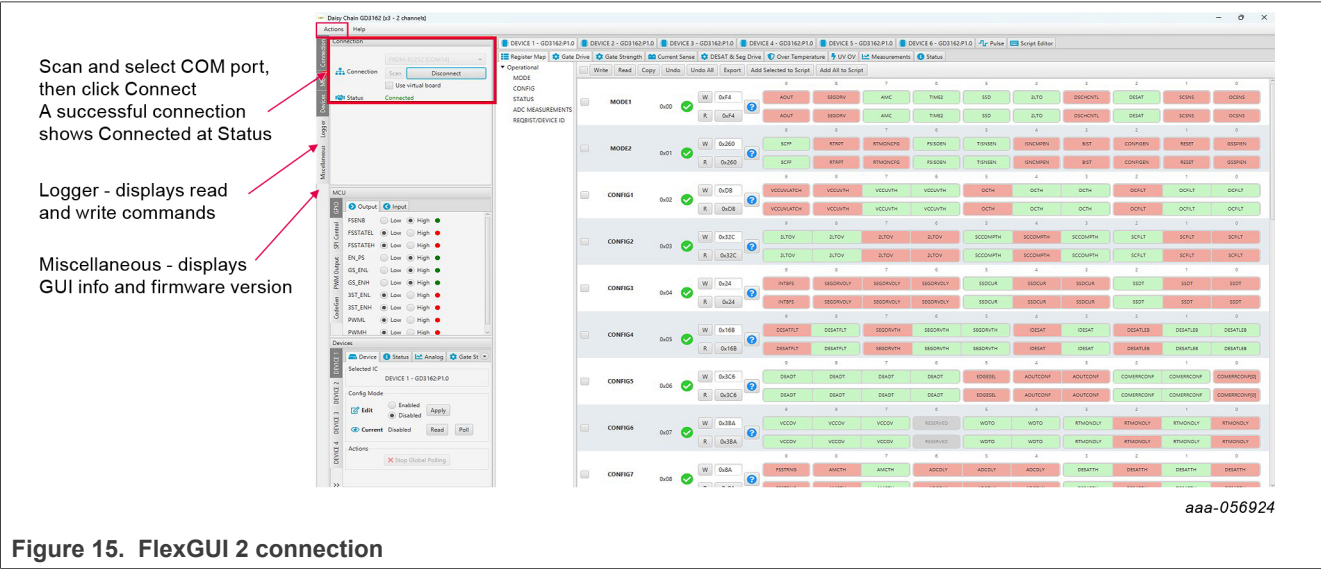
Set GUI actions and preferences

Access preferences from Actions menu at top left of GUI

Enable synchronized read and write to set both HS and LS devices simultaneously with same settings if desired

Enable Use register init value and Enable read after write and Enable to set read value to write value if desired (recommended)

aaa-055040

Figure 16. Actions and preferences settings

FSENB	Fail-safe mode enable (active LOW) (high side and low side)
FSSTATEL	Fail-safe state (low side)
FSSTATEH	Fail-safe state (high side)
EN_PS	Enable power supply (flyback) VCC on board (17 V high side and low side)
GS_ENL	Gate strength enable LOW (high side and low side)
GS_ENH	Gate strength enable HIGH (high side and low side)
3ST_ENL	Gate strength enable LOW 3-state (high side and low side)
3ST_ENH	Gate strength enable HIGH 3-state (high side and low side)
PWML	Pulse width modulation (low side)
PWMH	Pulse width modulation (high side)

Set logic level on gate drive and hardware inputs as desired.

aaa-055041

Figure 17. MCU GPIO output control

INTA and INTB fault indicators - interrupt
LOW means there is a fault latched

Interrupt A low side

Interrupt A high side

Interrupt B low side

Interrupt B high side

aaa-055042

Figure 18. MCU GPIO input

PWM output can be used to generate a continuous PWM
to both high-side devices and low-side devices

aaa-055043

Figure 19. MCU PWM output

Figure 20. Devices

Figure 21. GUI tabs
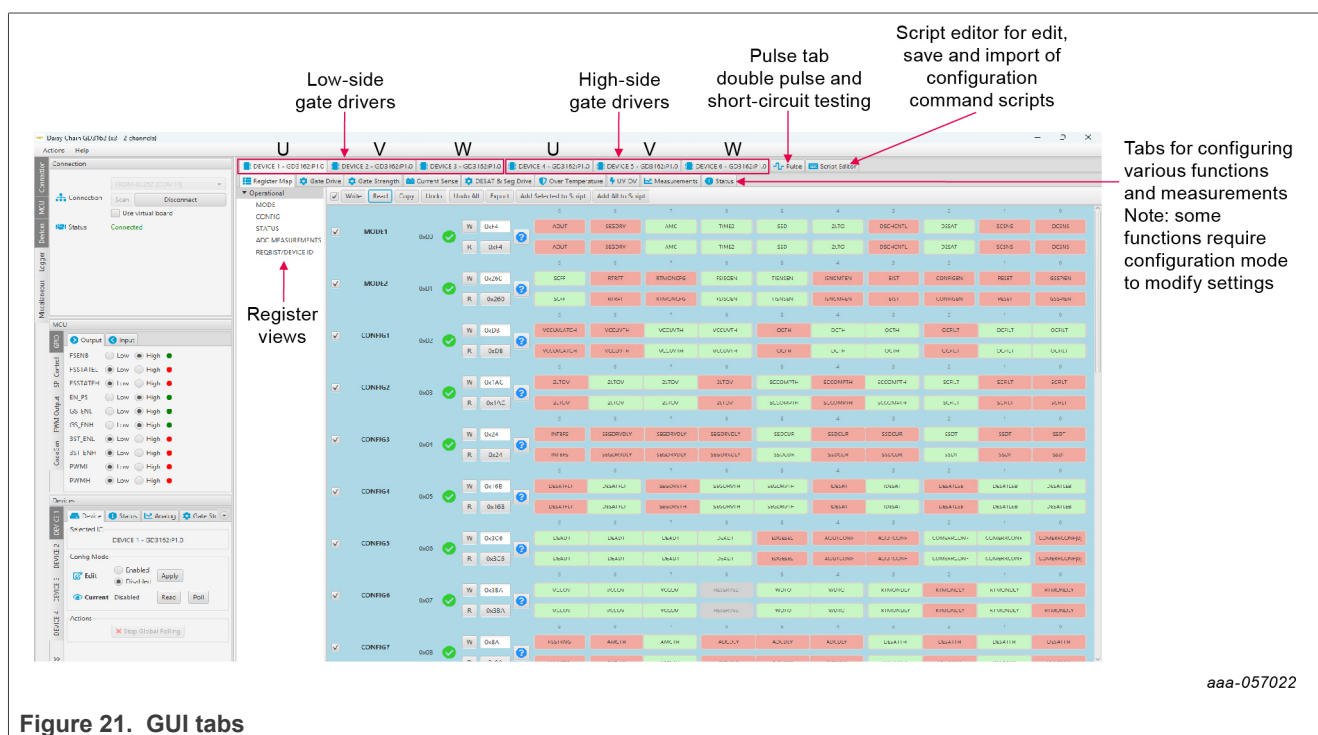
- Registers are grouped according to function; independent lines to read and write the registers
- Individual registers can be read by clicking the R button and can be written by using the W button
- Copy button to copy the read values to the write line; can be set to copy automatically
- Global register controls perform the selected command on all registers with the checkbox selected
- Add to Script adds current and selected register values to a script in the script editor window

Figure 22. GUI tabs continued
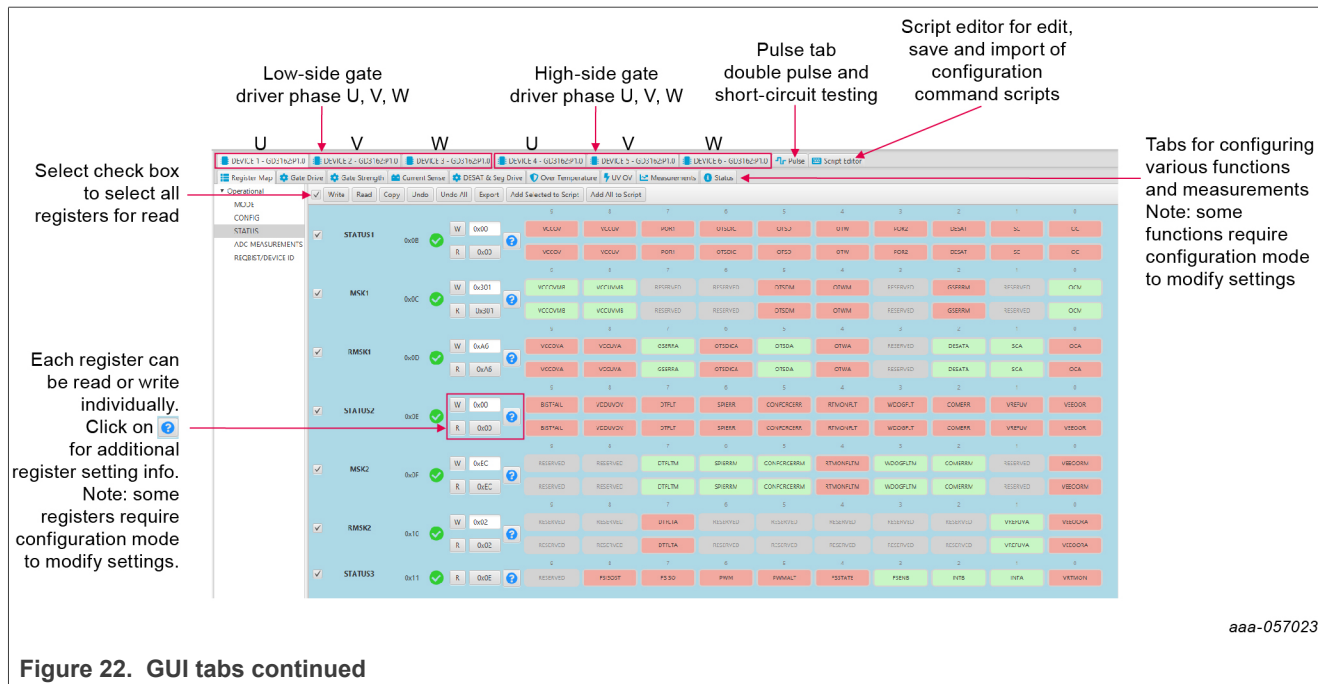
Gate Drive tab

- Allows setting of parameters related to the gate drive; controls are disabled when not in config mode
- Provides a more intuitive visual way to set parameters
- All settings are automatically synchronized with the register controls.
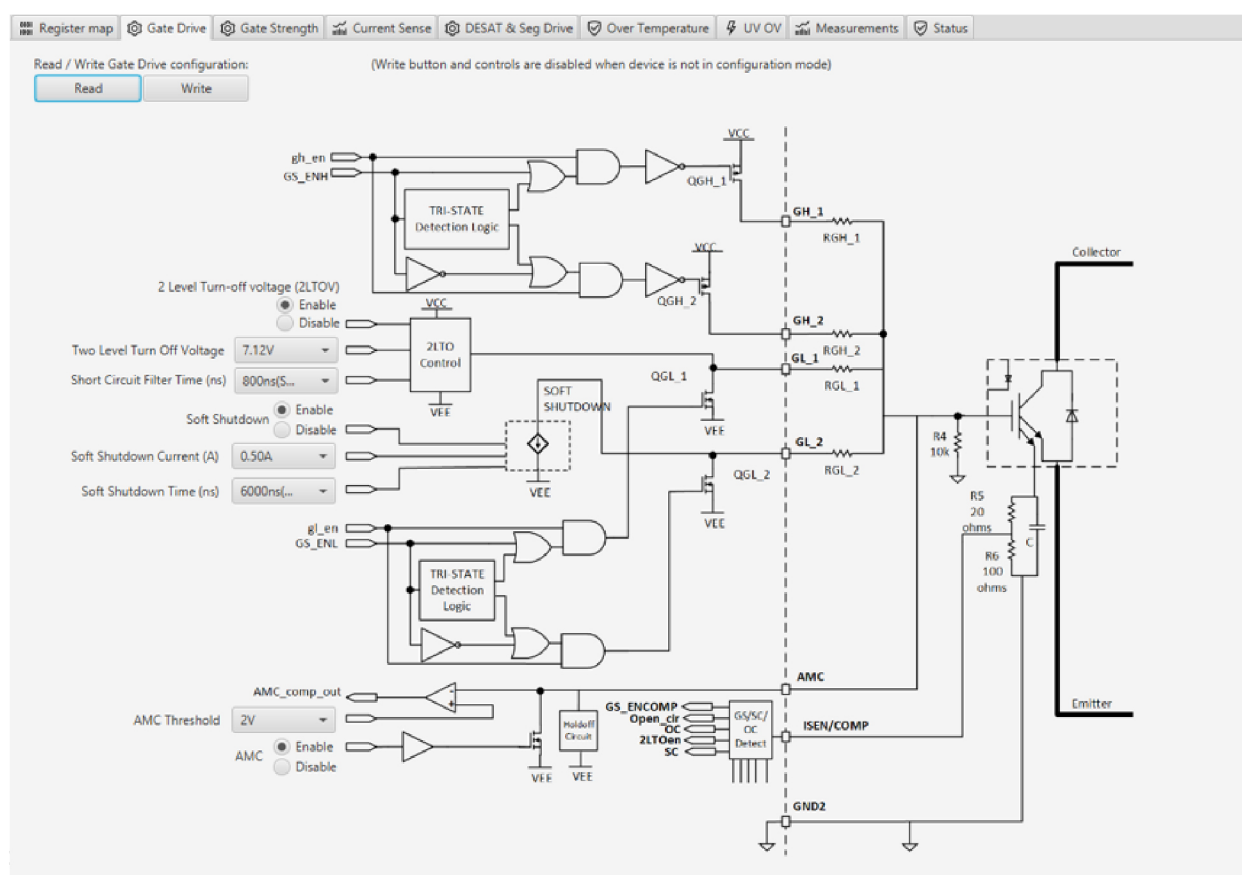
aaa-044992
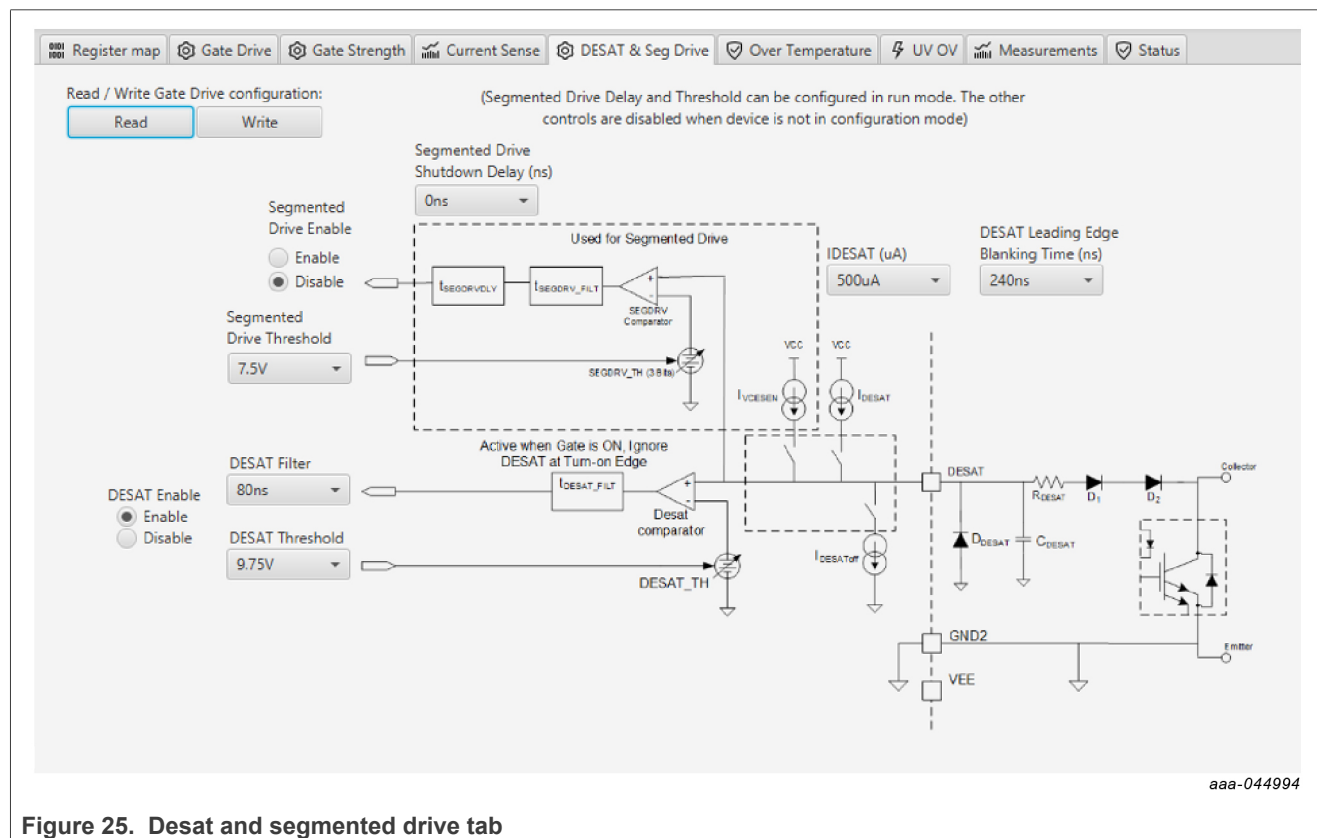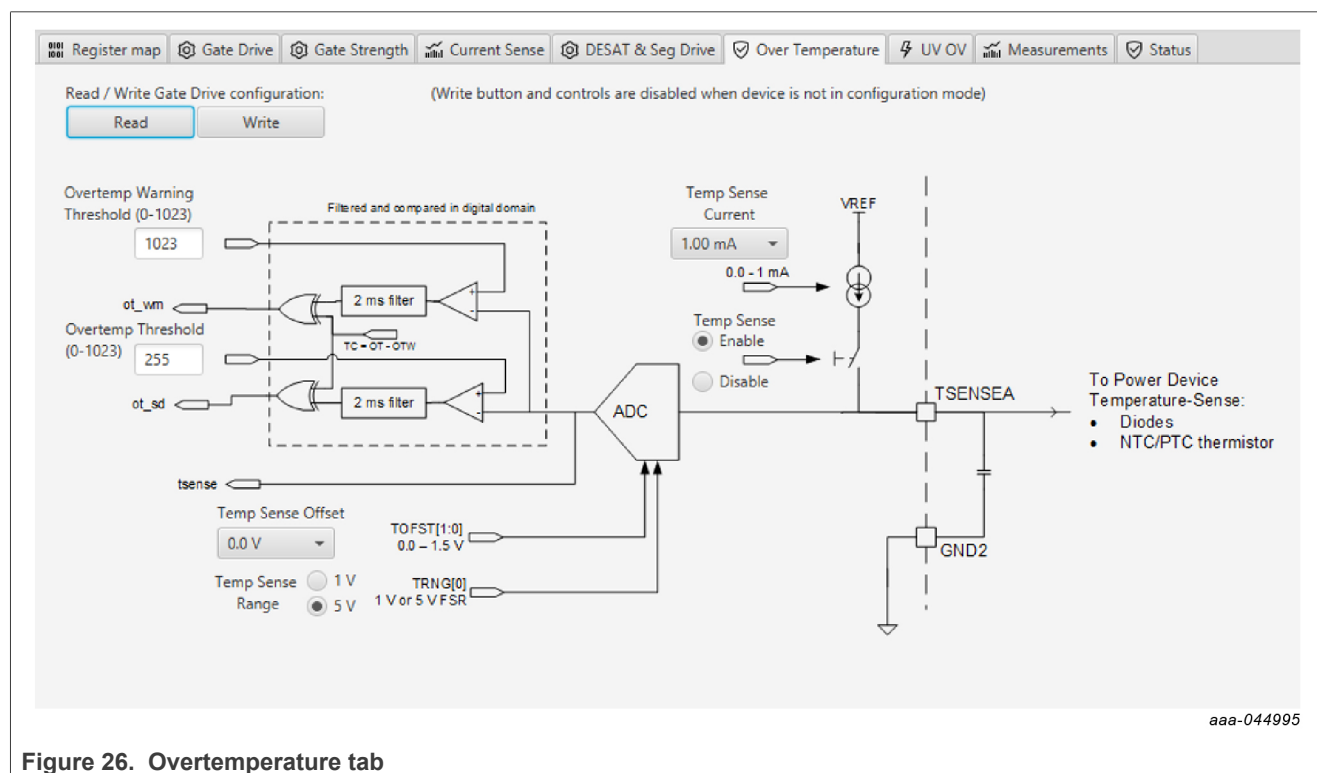
Figure 23. Gate drive tab

Current Sense tab

- Allows setting of parameters related to current sense
- Provides a more intuitive visual way to set parameters
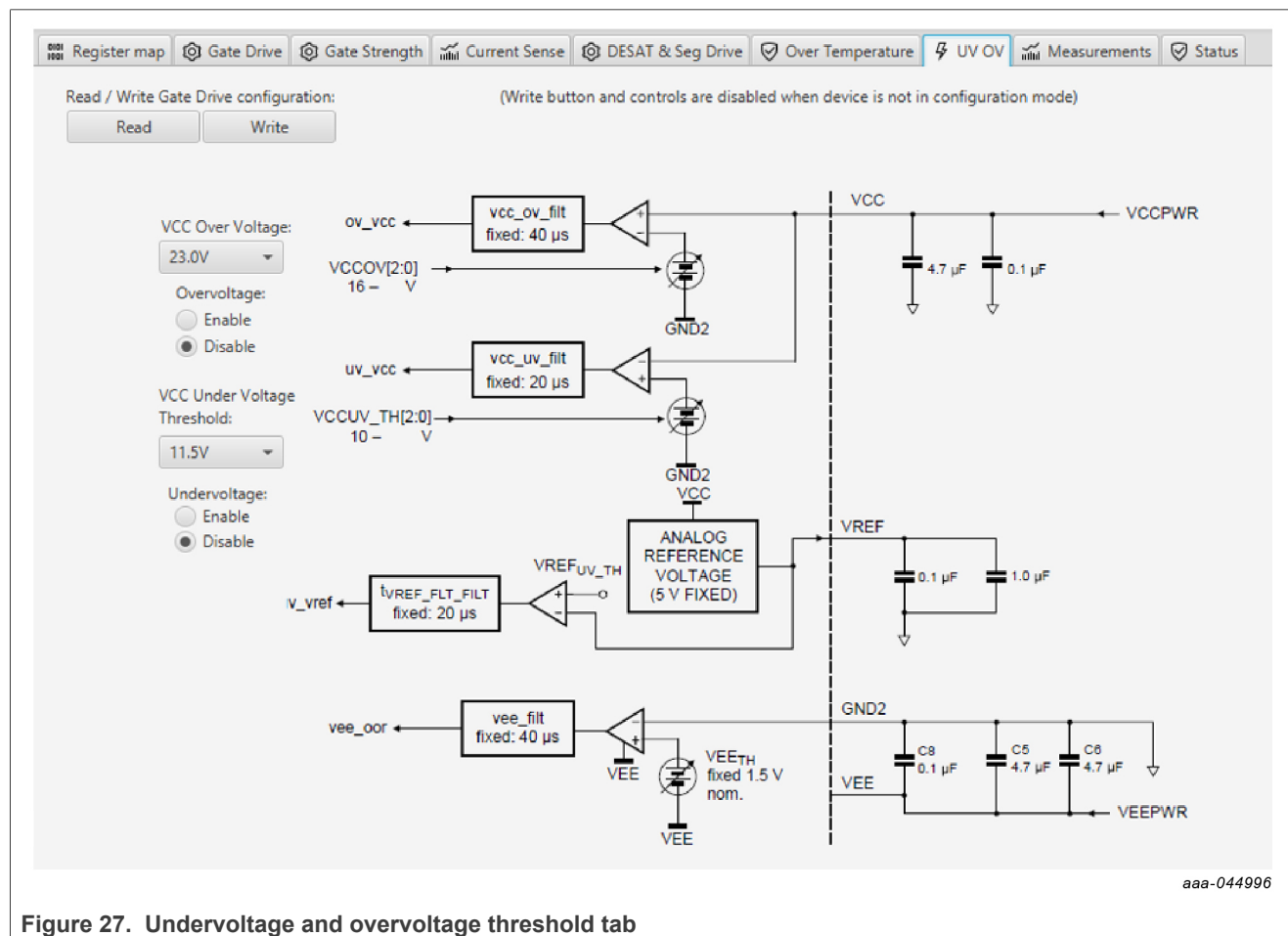- All settings are automatically synchronized with the register controls.
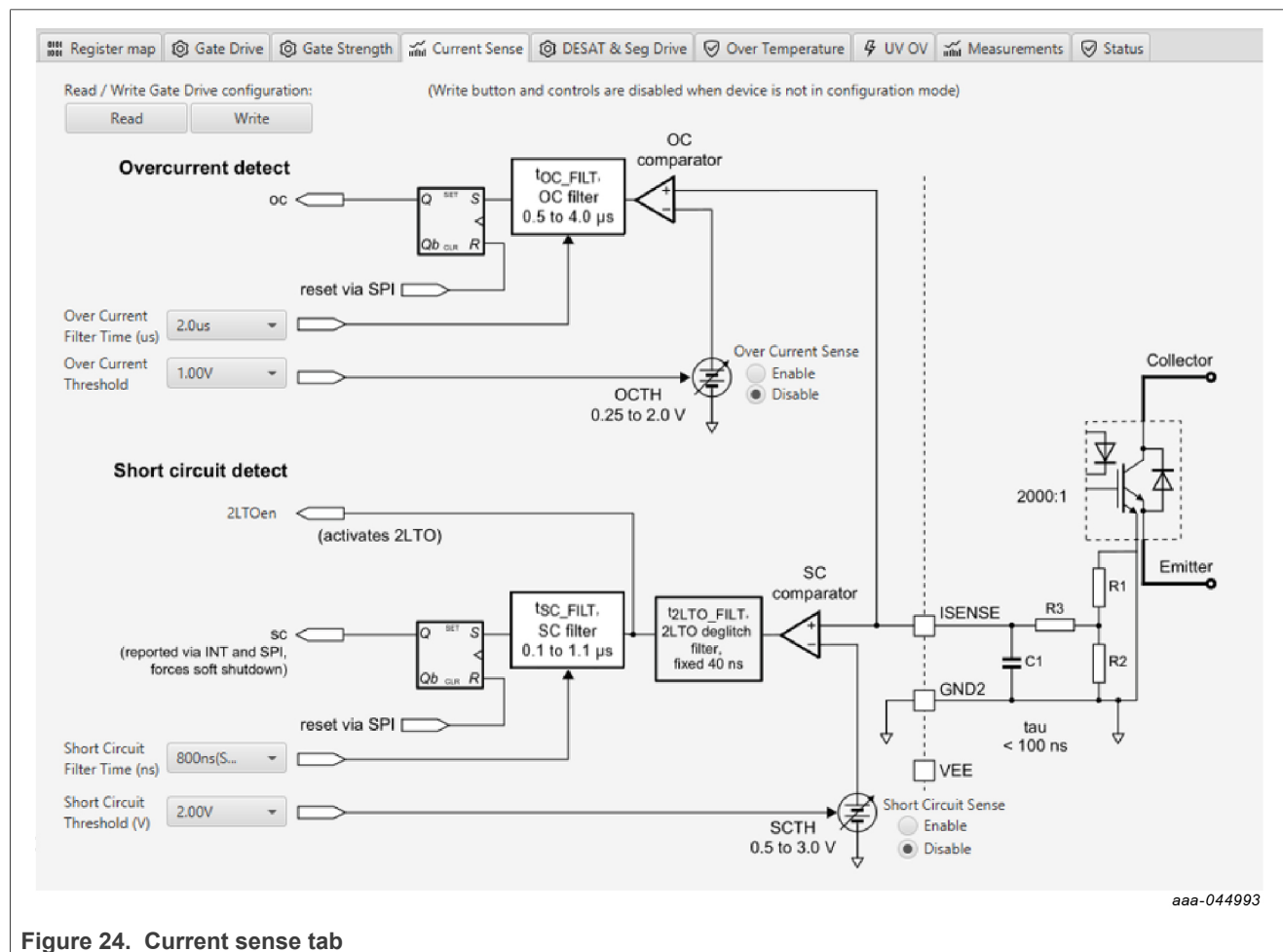
Figure 24. Current sense tab

UM11996

User manual

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Rev. 2.0 — 16 October 2024

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Document feedback

27 / 41

DESAT & Seg Drive tab

- Allows setting of parameters related to desat and segmented drive
- Provides a more intuitive visual way to set parameters
- All settings are automatically synchronized with the register controls.

aaa-044994

Figure 25. Desat and segmented drive tab

Overtemperature tab

- Allows setting of parameters related to overtemperature and overtemperature warning thresholds
- Provides a more intuitive visual way to set parameters
- All settings are automatically synchronized with the register controls.

Figure 26. Overtemperature tab

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User manual **Rev. 2.0 — 16 October 2024** Document feedback

29 / 41

Undervoltage and overvoltage threshold tab

- Allows setting of parameters related to undervoltage and overvoltage threshold
- Provides a more intuitive visual way to set parameters
- All settings are automatically synchronized with the register controls.

Figure 27. Undervoltage and overvoltage threshold tab

UM11996

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Document feedback

30 / 41

Measurements tab

• Allows monitoring and graphing of ADC and temperature values

Figure 28. Measurements tab

Pulse tab

- Used for double pulse, short circuit, and PWM testing
- Select desired t1, t2, and t3 timings for each test type; select enable then generate pulses

Note: *All phases can be used for performing double pulse tests. To enable short-circuit testing, resistors on PWMALT signals must be removed to disable dead time control on gate drivers.*
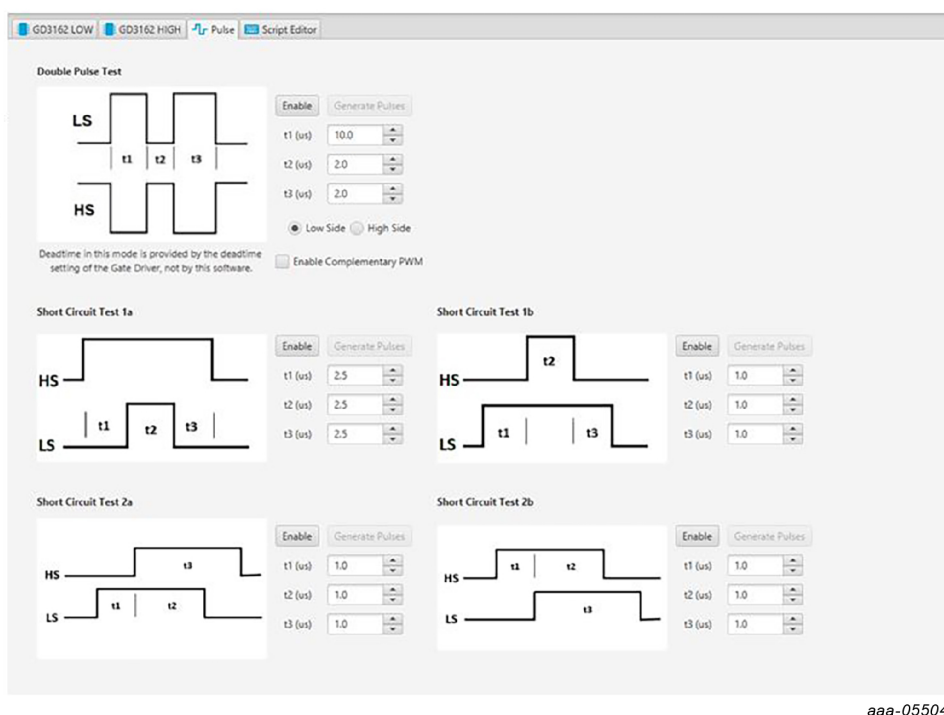
Figure 29. Pulse tab

Script editor tab

• Scripts can be used for setting up configurations on all devices and saved for reuse.

aaa-056925
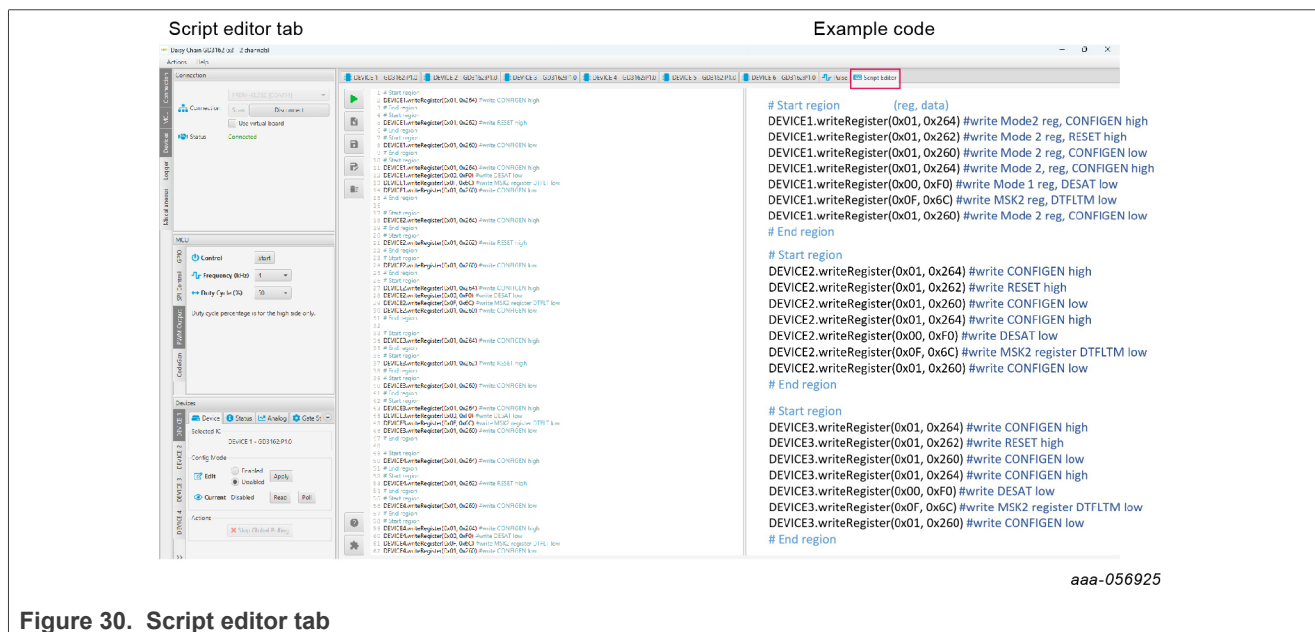
Figure 30. Script editor tab

7.4 Troubleshooting

Some common issues and troubleshooting procedures are detailed below. This is not an exhaustive list by any means, and additional debug may be needed:

Problem	Evaluation	Explanation	Corrective action(s)
Unable to establish COM port connection	Check USB cable is connected to KL25Z port on FRDM-KL25Z MCU	If the USB cable is not connected to PC USB and KL25Z port GUI will not be able to establish USB connection	Plug in USB cable to PC USB port and FRDM-KL25Z KL25Z port
	Incorrect firmware installed on FRDM-KL25Z MCU	If the incorrect firmware is installed on the FRDM-KL25Z MCU board GUI will not be able to establish USB connection	Go to step 5 in this user guide for installing FlexGUI 2 on your computer to locate firmware file in GUI download package and copy to FRDM-KL25Z through OpenSDA port on MCU board.
	Check the COM port setting on FlexGUI 2. The drop-down menu will show the various COM ports available.	Selecting the incorrect COM port in the COM port drop-down menu will not be able to establish USB connection.	Select an alternative COM in the COM port drop-down menu on FlexGUI 2.
No PWM output (no fault reported)	Check PWM jumper position on translator board	Incorrect PWM jumpers obstruct signal path but not report fault	Set PWMH_SEL (J4) and PWML_SEL (J5) jumpers properly, for desired control method: • 3.3 V to 5.0 V translator board reviewed in Section 6.4
	Check PWM control signal	Ensure that proper PWM signal is reaching GD3162	Monitor PWML (TP11) and PWMH (TP10) on translator board for commanded PWM state. Check position of jumpers J4 and J5 on translator board.
	Check FSENB status (see GD3162 pin 15, STATUS3)	PWM is disabled when FSENB = LOW	Set pin FSENB = HIGH (pin 15) to continue
	Check CONFIG_EN bit (MODE2)	PWM is disabled when CONFIG_EN is logic 1	Write CONFIG_EN = logic 0 to continue

Problem	Evaluation	Explanation	Corrective action(s)
No PWM output (fault reported)	Check VGE fault (VGE_FLT)	A short on IGBT or SiC module gate, or too low of VGEMON delay setting causes VGE fault, locking out PWM control of the gate.	Clear VGE_FLT bit (STATUS2) to continue. Increase VGEMON delay setting (CONFIG6). If safe operating condition can be guaranteed, set VGE_FLTM (MSK2) bit to logic 0, to mask fault.
	Check for short-circuit fault (SC) in STATUS1 register	SC is a severe fault that disables PWM. SC fault cannot be masked	Clear SC fault to continue. Consider adjusting SC fault settings on GD3162: • Adjust short-circuit threshold setting (CONFIG2) • Adjust short-circuit filter setting (CONFIG2)
PWM output is good, but with persistent fault reported	Check for dead time fault (DTFLT) in STATUS2 register	Dead time is enforced, but fault indicates that PWM controls signals are in violation	Clear DTFLT fault bit (STATUS2). Check PWMHSEL (J10) and PWMLSEL (J14) are configured to bypass dead time faults. Consider adjusting dead time settings on GD3162: • Change mandatory PWM dead time setting (CONFIG5) • Mask dead time fault (MSK2)
	Check for overcurrent (OC) fault in STATUS1 register	OC fault latches, but does not disable PWM. OC fault cannot be masked.	Clear OC fault bit (STATUS1). Adjust OC fault detection settings on GD3162: • Adjust overcurrent threshold setting (CONFIG1) • Adjust overcurrent filter setting (CONFIG1)
PWM or FSSTATE rising edge has longer delay than falling edge	Check translator output voltage versus GD3162 VDD voltage	Low translator output voltage (compared with correct VDD at GD3162) causes the high threshold at the GD3162 pin to be crossed later than commanded	Check translator output voltage selection (J3) is configured to the same level as the GD3162 VDD Check VCCSEL supply or translator outputs on the translator board for excessive loading or supply droop/pulldown
WDOG_FLT reported on startup	Check VSUP and VCC are powered	On initialization, watchdog fault is reported when one die is powered up before the other	Check VSUP and VCC both have power applied. Clear WDOG_FLT bit (STATUS2) to continue.
SPIERR reported on startup	Check KL25Z/translator connection	On initialization, SPIERR can occur when the SPI bus is open, or when GD3162 IC is powered up before the translator (which provides CSB).	Clear SPIERR fault to continue. Reinitialize power to GD3162 after translator is powered (over USB).
SPIERR reported after SPI message	Check bit length of message sent	There is SPIERR if SCLK does not see a n*24 multiple of cycles	Use 24-bit message length for SPI messages
	Check CRC	SPIERR faults if CRC provided in sent message is not good	Use FlexGUI to generate commands with valid CRC. The command can be copied in binary or hexadecimal and sent from another program.
	Check for sufficient dead time between SPI messages	SPIERR fault bit is set when the time between SPI messages (txfer_delay) received is too short. Minimum required delay time is 19 µs.	Check time between CSB rising edge (old message end) and CSB falling edge (new message start) during normal SPI read, and ensure transfer delay dead time check. SPIERR can also be cleared in BIST.
VCCREGUV reported on startup	Check VCCREG potential	Caused by low VCC	Clear VCCREGUV fault bit (STATUS1). Tune VCC-GNDISO potential with power supply set resistor (R51).

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User manual
Rev. 2.0 — 16 October 2024
Document feedback

34 / 41

Problem	Evaluation	Explanation	Corrective action(s)
VREFUV reported on startup	Check HV domain is powered correctly	Related to slow rise time of VCC supply on HV domain, or failed VREF regulator	Clear VREFUV bit (STATUS2). Reset HV domain supply if fault bit does not clear.
	Check VCC for undervoltage condition	Low VCC is visible indirectly through other HV domain faults	Tune VCC-GNDISO using R51 feedback
VCCOV fault reported on startup	Check VEE level on suspect domain.	If VEE level is not at desired negative voltage it could cause excessive VCC level.	Check Zener diode in power supply circuit for proper value in setting VEE level. Clear VCCOV bit (STATUS1) to continue.
	Check VCC-GNDISO potential	PWM is disabled during a VCC overvoltage (20 V nom.)	Tune VCC-GNDISO potential to suitable level with power supply set resistor (R51). Clear VCCOV bit (STATUS1) to continue.
No PWM during short circuit test	Check PWMxSEL jumpers	Incorrect configuration of PWMALT pins prevent short-circuit test by enforcing dead time	PWMALT resistors must be unpopulated to disable dead time control for short circuit testing. See Pulse tab in Section 7.3.
Bad SPI data, appears to repeat previous response	Check VSUP/VDD for undervoltage condition	VDD_UV latches SPI buffer contents, preventing updated fault reporting.	Check voltage provided at VDD pin (pin 3). On each read, compare the address from the sent command and response (a difference indicates that the SPI response is latched due to inactive). Read multiple addresses to ensure a good comparison.
	Check EN_PS is set to HIGH in FlexGUI 2; see Figure 17	VCC/VEE can be enabled/disabled in software.	EN_PS in GPIO output tab on FlexGUI 2; see Figure 17
	Check VCC for undervoltage	Unpowered VCC prevents HV domain from updating data	Tune VCC-GNDISO using R51 feedback

8   Configuring the hardware

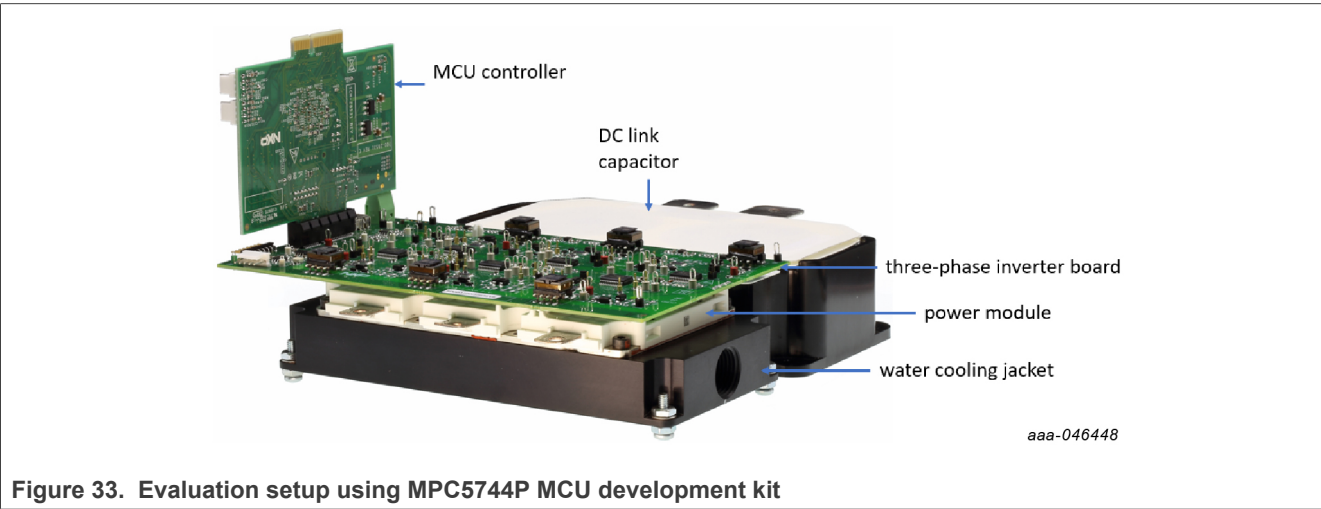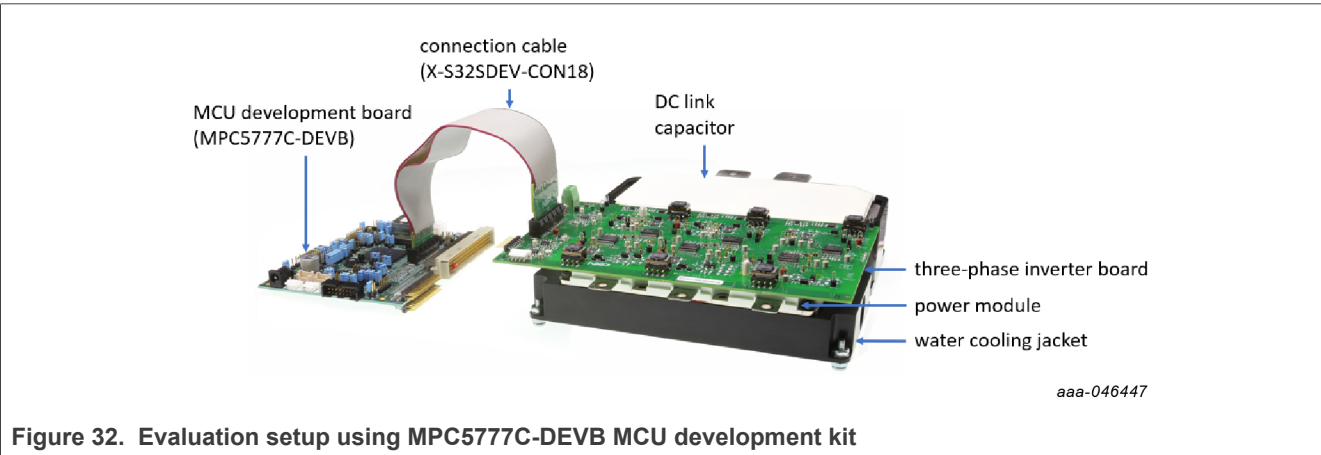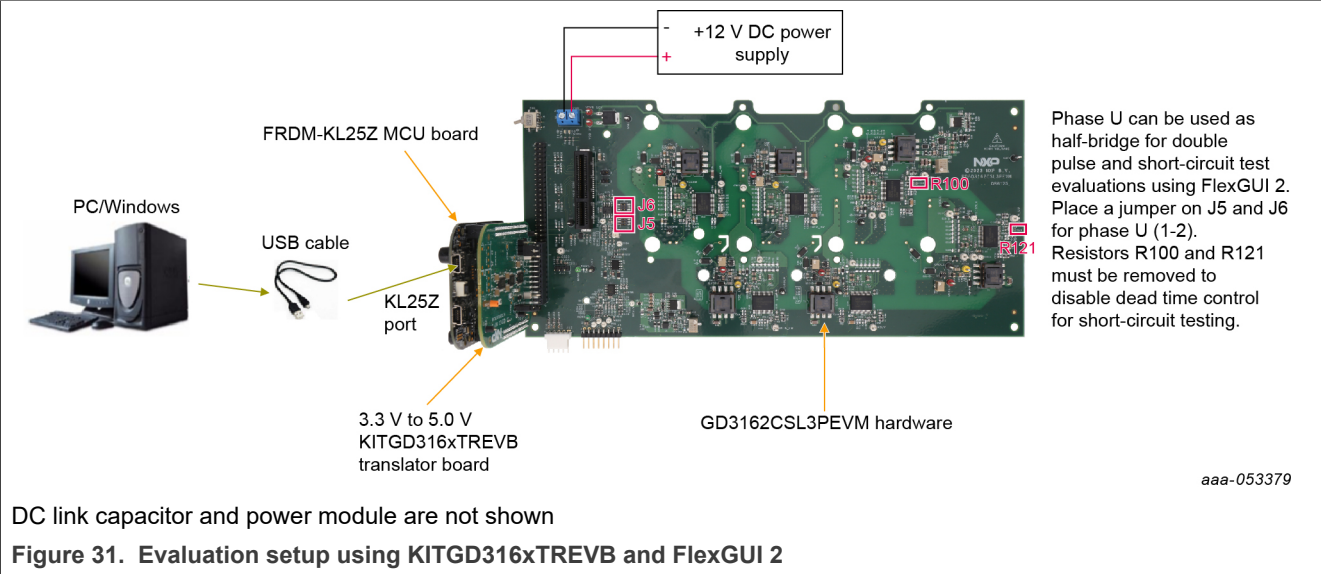RDGD3162CSL3PEVM with KITGD316xTREVB attached as shown in Figure 31 using Windows-based PC and FlexGUI software.

Note: Double pulse and short-circuit testing can be conducted on all phases with proper jumper settings. See FlexGUI 2 Pulse tab, Figure 29.

Suggested equipment needed for test:

- Rogowski coil high-current probe
- High-voltage differential voltage probes
- High sample rate digital oscilloscope with probes
- DC link capacitor compatible with Bosch CSL B-sample power module
- Bosch CSL B-sample SiC power module
- Windows-based PC
- High-voltage DC power supply for DC link voltage
- Low-voltage DC power supply for VPWR
  – +12 V DC gate drive board low-voltage domain
- Voltmeter for monitoring high-voltage DC link supply
- Load coil for double pulse testing (phase U)

Note: To enable short-circuit testing on phase U, two resistors (R100, R121) must be removed from PWMALT phase U signals to disable dead time control on phase U gate drivers.

Phase U can be used as half-bridge for double pulse and short-circuit test evaluations using FlexGUI 2. Place a jumper on J5 and J6 for phase U (1-2). Resistors R100 and R121 must be removed to disable dead time control for short-circuit testing.

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DC link capacitor and power module are not shown

Figure 31. Evaluation setup using KITGD316xTREVB and FlexGUI 2

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Figure 32. Evaluation setup using MPC5777C-DEVB MCU development kit

aaa-046448

Figure 33. Evaluation setup using MPC5744P MCU development kit

9 Schematic, board layout, and bill of materials

The schematic, board layout, and bill of materials for the RDGD3162CSL3PEVM reference design are available at http://www.nxp.com/RDGD3162CSL3PEVM.

10 References

[1] RDGD3162CSL3PEVM detailed information on this board, including documentation, downloads, and software and tools http://www.nxp.com/RDGD3162CSL3PEVM

[2] GD3162 product information on advanced single-channel gate driver for IGBT/SiC http://www.nxp.com/GD3162

[3] MPC5777C ultra-reliable MCU for automotive and industrial engine management http://www.nxp.com/MPC5777C

[4] MPC5744P ultra-reliable MCU for automotive and industrial safety applications http://www.nxp.com/MPC574xP

[5] MPC5775B/E-EVB low-cost development board for battery management and inverter http://www.nxp.com/MPC5775B-E-EVB

[6] https://www.bosch-semiconductors.com/power-semiconductors-and-modules/csl-1200-v-pinfin/

11 Revision history

Table 8. Revision history

Document ID	Release date	Description
UM11996 v.2.0	16 October 2024	update for FlexGUI 2
UM11996 v.1	22 November 2023	initial version

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Contents